

Compal Confidential

Model Name : B4DBU(WIFI) / B4DBG(LTE)
File Name : LA-D301P
BOM P/N:43

Compal Confidential

B4DBU(WIFI) / B4DBG(LTE)
M/B Schematics Document

Skylake U Processor + DDR4 + Nvidia N16X

2015-12-09
Rev:1.0

ZZZ
LA-D301P
DAA0008G000
DA2@

ZZZ
LS-D303P FUN/B
DA400299000
DA2@

ZZZ
LS-D302P USB/B
DA6001HX000
DA2@

ZZZ
LS-A133P
DA600101010
DA2@

ZZZ
LS-D301P LID/B
DA400272000
DA2@

ZZZ
LS-B734P
DA6001B8010
DA2@

ZZZ
HDMI LOGO
RO0000003HM
HDMI@

ZZZ
LS-B730P
DA4001YF010
DA2@

ZZZ
DAZ PCB
DAZ11B00100
DAZ@

UC1
S IC FJ8066201931104 SR2EU D1 2.3G ABO!
CPU_2NB0@
SA000092NB0

UC1
S IC FJ8066201930409 SR2EY D1 2.3G ABO!
CPU_2OB0@
SA000092OB0

UC1
S IC FJ8066201930408 SR2EZ D1 2.5G ABO!
CPU_2P90@
SA000092P90

UC1
S IC FJ8066201924931 QJKM D1 2.4G ABO!
CPU_2T50@
SA000092T50

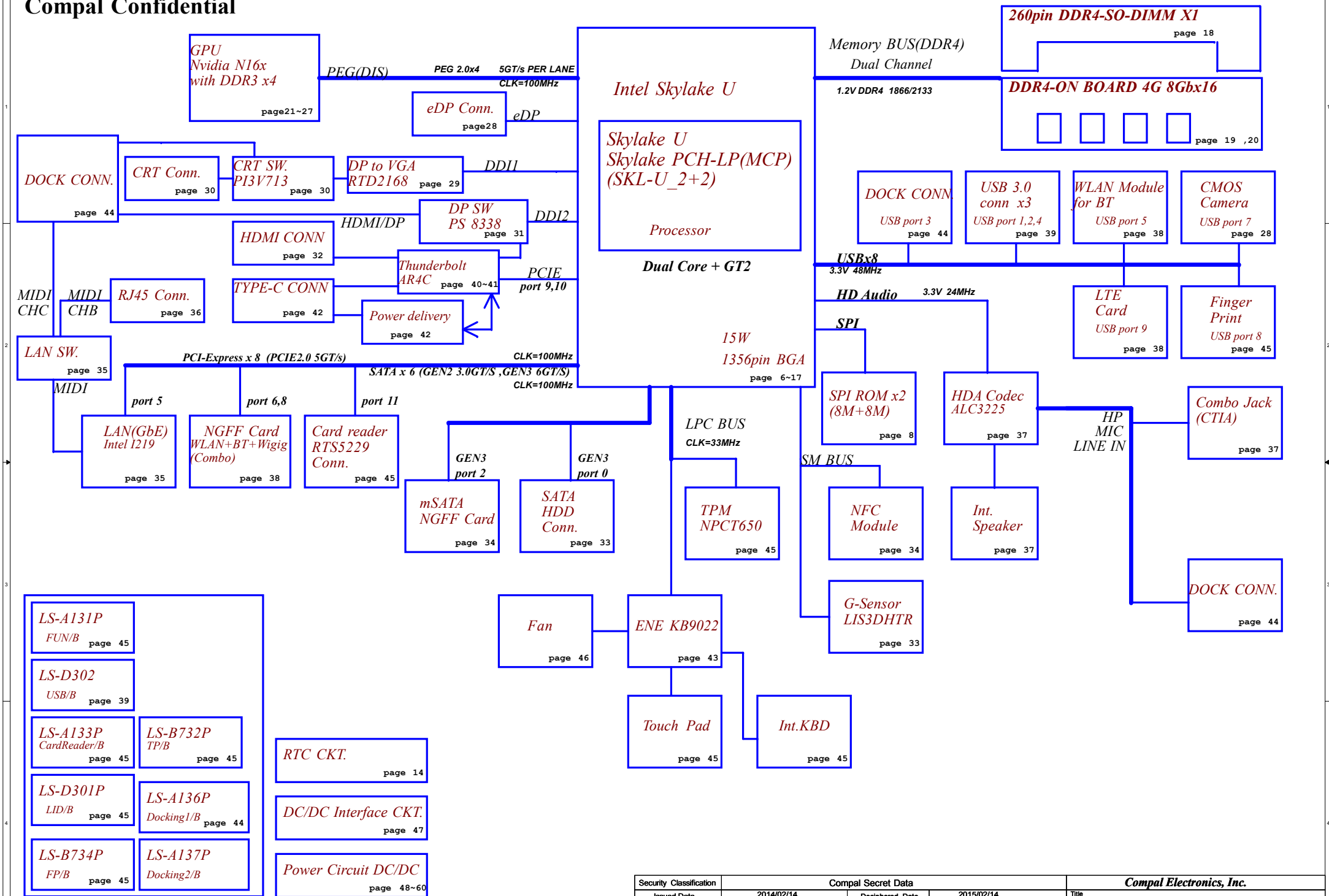
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CPU_2T80@
SA000092T80

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CPU_2U70@
SA000092U70

UC1
S IC FJ8066201924950 SR2F1 D1 2.6G ABO!
CPU_2U80@
SA000092U80

Security Classification		Compal Secret Data		Compal Electronics, Inc.		
Issued Date	2014/02/14	Deciphered Date	2015/02/14	Title		
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				Size	Document Number	Rev
				Custom	LA-D301P	0.1
				Date:	Thursday, December 17, 2015	Sheet 1 of 63

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				Custom	LA-D301P	0.1
				Date:	Thursday, December 17, 2015	Sheet 2 of 63

Board ID Table for AD channel

Vcc	3.3V +/- 5%				
Ra	100K +/- 5%				
Board ID	Rb	V _{BI} D min	V _{BI} D typ	V _{BI} D max	EC AD3
0	0	0 V	0 V	0.300 V	0x00 - 0x0B
1	12K +/- 1%	0.347 V	0.345 V	0.360 V	0x0C - 0x1C
2	15K +/- 1%	0.423 V	0.430 V	0.438 V	0x1D - 0x26
3	20K +/- 1%	0.541 V	0.550 V	0.559 V	0x27 - 0x30
4	27K +/- 1%	0.691 V	0.702 V	0.713 V	0x31 - 0x3B
5	33K +/- 1%	0.807 V	0.819 V	0.831 V	0x3C - 0x46
6	43K +/- 1%	0.978 V	0.992 V	1.006 V	0x47 - 0x54
7	56K +/- 1%	1.169 V	1.185 V	1.200 V	0x55 - 0x64

BOM Structure Table

BOM Option Table		BOM Option Table	
Item	BOM Structure	Item	BOM Structure
Unpop	@	dGPU	VGA@
Connector	CONN@	SAMSUNG DDR4	X76SAM@
EMC requirement	EMC@	N16S-GT	SGT@
EMC requirement depop	@EMC@	Without WiGi Funct i on	NOWG@
EMI requirement	@EMC@/EMI@	HDD Redriver	X76TI@/X76PAR@
Thunderbolt Funct i on	TBT@	GPU CG6 funct i on	VGM@
RF requirement	@RF@/RF@	VRAM BOM Select	X76@
LTE Funct i on	3G@	Single/Dual Rank	SR@/DR@ (DR@ is not been used in this project)
UMA only	UMA@		
VPRO Funct i on	VPRO@/NOVPRO@		
VGA EMI Requirement	@VGA_EMI@/VGA_EMI@		
VGA UNPOP	@VGA@		
VGA RF Requirement	@RF@_VGA@	PD Funct i on	PD@
VGA Power	22@/23E@	CPU Code	QH7Y@
GC6 Funct i on	GC6@/NOGC6@/NGC6	CPU Code	QH7Y@
INTEL CMC	CMC@		
ESPI	ESPI @		

I2C Address Table

BUS	Device	Address(7 bit)	Address(8bit)	
			Write	Read
I2C_0 (+3VS)	Reserved (Touch Panel)			
I2C_1 (+3VS)	TM-P2969-001 (TP)	0x2C		
	SB8787-1200 (TP-ELAN)	0x16		
SOC_SMBCLK +3VS	DIMM1	0xA0		
	DIMM2	0xA4		
	LIS3DHTR(G-Sensor)	0x30		
SOC_SML1CLK +3VS	N16S-GT (VGA)	0x9E		
	PCH-LP (SOC)	0x90		
EC_SMB_CK1 +3VLP	BQ24780 (Charger IC)	0x12		
	BATTERY PACK	0x16		
SOC_SML0CLK +3VS	LAN	0xC8		
	NFC	0x28		

43 level BOM table

43 Level	Description	BOM Structure
431A0NBOL01	SMT MB AD301 B4DBG QJFC 2.3G UMA HDMI	3G@/CMC@/DA2@/SR@/EMC@/EMI@/ESD@/HDMI@/NOVPRO@/PD@/TBT@/UMA@/X76PAR@/X76SAM@/RF@
431A0NBOL02	SMT MB AD301 B4DBG QJ8M 2.4G UMA HDMI	3G@/CMC@/DA2@/SR@/EMC@/EMI@/ESD@/HDMI@/NOVPRO@/PD@/TBT@/UMA@/X76PAR@/X76SAM@/RF@
431A0NBOL03	SMT MB AD301 B4DBG QJKP 2.3G DIS HDMI	3G@/CMC@/DA2@/SR@/EMC@/EMI@/ESD@/GC6@/HDMI@/PD@/SGT@/TBT@/VGA@/VGA_EMI@/VPRO@/X76PAR@/X76SAM@/RF@
431A0NBOL04	SMT MB AD301 B4DBG QJKK 2.5G DIS HDMI	3G@/CMC@/DA2@/SR@/EMC@/EMI@/ESD@/GC6@/HDMI@/PD@/SGT@/TBT@/VGA@/VGA_EMI@/VPRO@/X76PAR@/X76SAM@/RF@

Power State

STATE	SIGNAL	SLP_S3#	SLP_S4#	SLP_S5#	+VALW	+V	+VS	Clock
S0 (Full ON)		HIGH	HIGH	HIGH	ON	ON	ON	ON
S3 (Suspend to RAM)		LOW	HIGH	HIGH	ON	ON	OFF	OFF
S4 (Suspend to Disk)		LOW	LOW	HIGH	ON	OFF	OFF	OFF
S5 (Soft OFF)		LOW	LOW	LOW	ON	OFF	OFF	OFF

BOARD ID Table

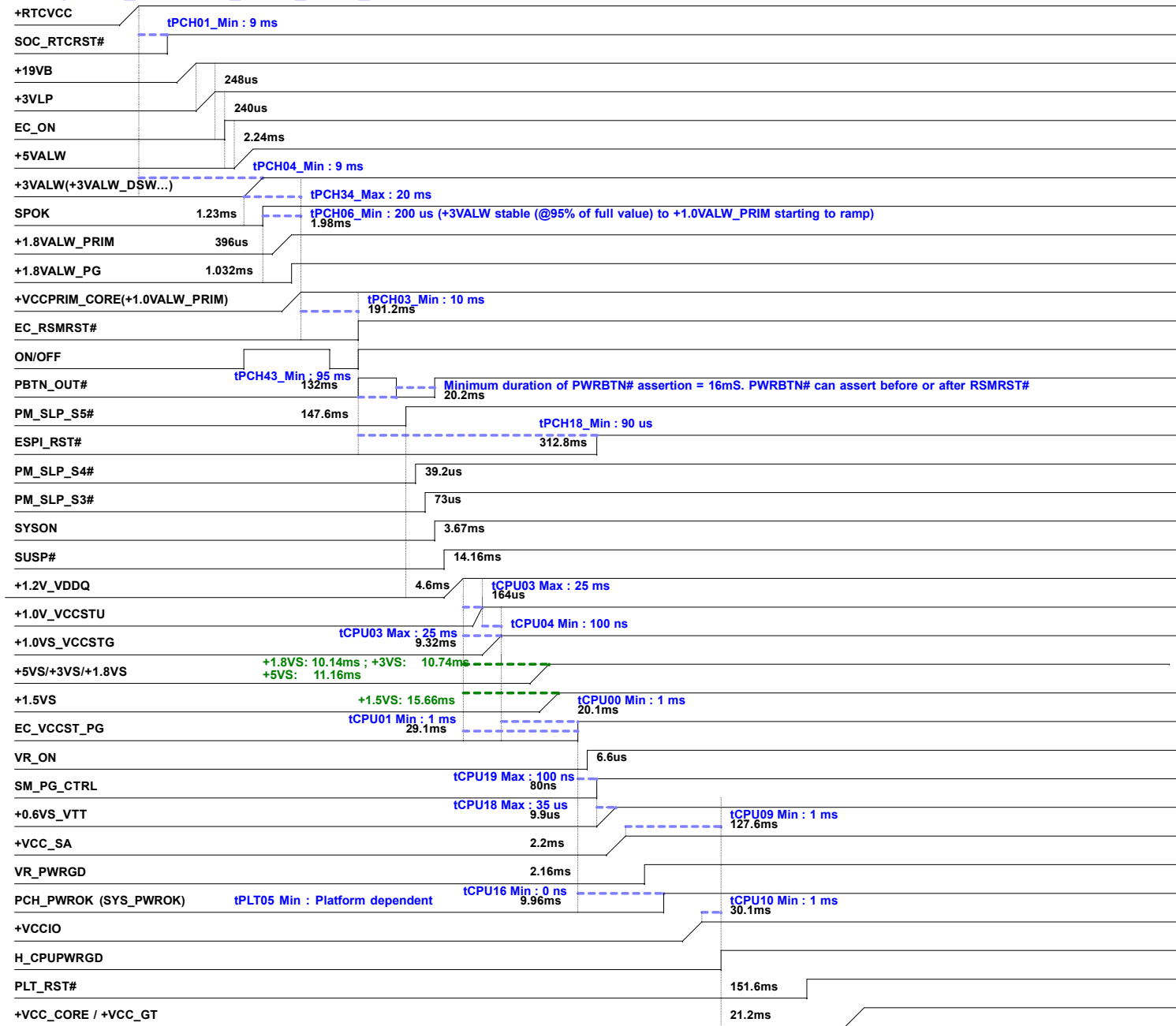
Board ID	PCB Revision
0	0.1
1	0.2
2	0.3
3	1.0
4	
5	
6	
7	

Voltage Rails

Power Plane	Description	S0	S3	S4/S5
+19V_VIN	Adapter power supply	N/A	N/A	N/A
+17.4V_BATT	Battery power supply	N/A	N/A	N/A
+19VB	AC or battery power rail for power circuit.	N/A	N/A	N/A
+VCC_CORE	Processor IA Cores Power Rail	ON	OFF	OFF
+VCC_GT	Processor Graphics Power Rails	ON	OFF	OFF
+VCC_SA	System Agent power rail	ON	OFF	OFF
+0.6VS_VTT	DDR +0.6VS power rail for DDR terminator .	ON	OFF	OFF
+1.0VALW_PRIM	+1.0V Always power rail	ON	ON	ON*1
+1.0V_VCCSTU	Sustain voltage for processor in Standby modes	ON	ON	OFF
+VCCIO	CPU IO power rail	ON	OFF	OFF
+1.0VS_VCCSTG	+1.0VALW_PRIM Gated version of VCCST	ON	OFF	OFF
+1.2V_VDDQ	DDR4 +1.2V Power Rail	ON	ON	OFF
+1.8VALW_PRIM	+1.8V Always power rail	ON	ON	ON*1
+1.8VS	System +1.8V power rail	ON	OFF	OFF
+3VLP	+19VB to +3VLP power rail for suspend power	ON	ON	ON
+3VALW	System +3VALW always on power rail	ON	ON	ON*1
+3VS	System +3V power rail	ON	OFF	OFF
+5VALW	+5V Always power rail	ON	ON	ON
+5VS	System +5V power rail	ON	OFF	OFF
+RTCVCC	RTC Battery Power	ON	ON	ON
+1.05VSDGPU	+1.05VS power rail for GPU	ON	OFF	OFF
+1.5VSDGPU	+1.5VS power rail for GPU	ON	OFF	OFF
+3VSDGPU_AON	+3VS power rail for GPU(AON rails)	ON	OFF	OFF
+3VSDGPU_MAIN	+3VS power rail for GPU GC62.0	ON	OFF	OFF
+VGA_CORE	Core power for descrete GPU	ON	OFF	OFF
+2.5V	DDR4 +2.5V Power Rail	ON	ON	OFF
Note : ON*1 means power plane is ON only when WOL enable and RTC wake at BIOS setting, otherwise it is OFF.				



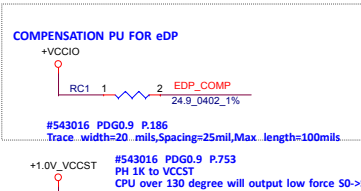
PWR Sequence_SKL-U2+2_DDR4_Value_NON CS



Functional Strap Definitions

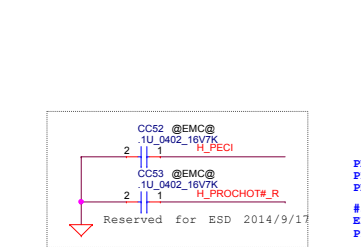
#543016 PDG0.9 P.775

DDPB_CTRLDATA/ GPP_E19 (Internal Pull Down):
DDPC_CTRLDATA/ GPP_E21 (Internal Pull Down):
DDPD_CTRLDATA/ GPP_E23 (Internal Pull Down):
(Sampled:Rising edge of PCH_PWROK)
Display Port B/C/D Detected
0 =Port is not detected.
1 =Port is detected.



#543016 PDG0.9 P.186
Trace width=20 mils,Spacing=25mil,Max.length=100mils
AR HDMI D08

#543016 PDG0.9 P.753
PH 1K to VCCST
CPU over 130 degree will output low force S0>S5



Reserved for ESD 2014/9/17

PDG0.9 P.771
PROC_POPIRCOMP/PCH_OPIRCOMP
PD 50ohm

#544669 CRB RVP7 1.0
EDRAM_OPIO_RCOMP/EDPIO_RCOMP
PD50ohm

RC1 1 24.9k 0.402% 1%
RC2 1 1k 0.402% 5%

RC3 1 1k 0.402% 5%

RC4 1 499k 0.402% 1%

RC5 2 1 49.9 0.402% 1% CPU_POPIRCOMP
RC6 2 1 49.9 0.402% 1% PCH_OPIRCOMP
RC7 2 1 49.9 0.402% 1% EDRAM_OPIO_RCOMP
RC8 2 1 49.9 0.402% 1% EDPIO_RCOMP

RC9 1 1k 0.402% 5% XDP_SPI_SI

RC10 1 1k 0.402% 5% XDP_ITP_PMODE

RC11 2 1 51 0.402% 5% SOC_XDP_TMS

RC12 2 1 51 0.402% 5% SOC_XDP_TDI

RC13 2 1 51 0.402% 5% SOC_XDP_TDO

RC14 2 1 51 0.402% 5% SOC_XDP_TRST#

RC15 2 1 51 0.402% 5% SOC_XDP_TDO

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RC22 2 1 51 0.402% 5% SOC_XDP_TDO

RC23 1 1k 0.402% 5% XDP_HOOK0

RC24 2 1 51 0.402% 5% SOC_XDP_TDO

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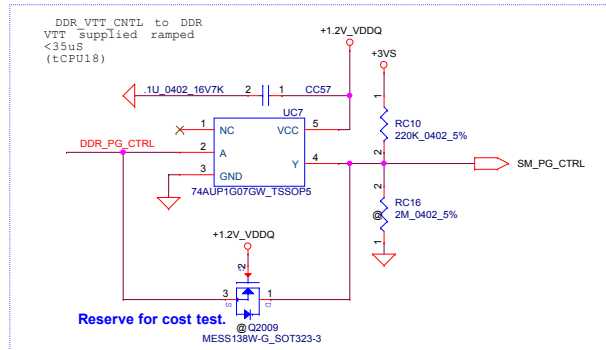
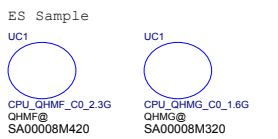
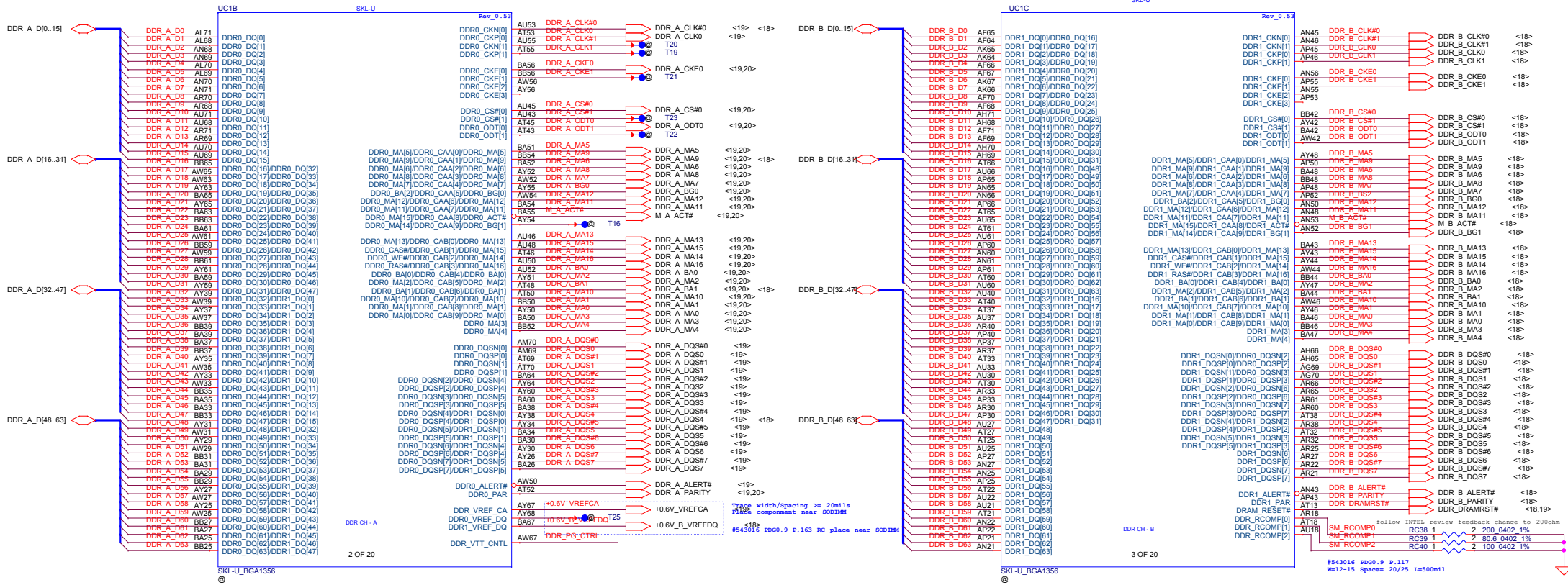
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RC195 2 1 51 0.402% 5% SOC_XDP_TDO

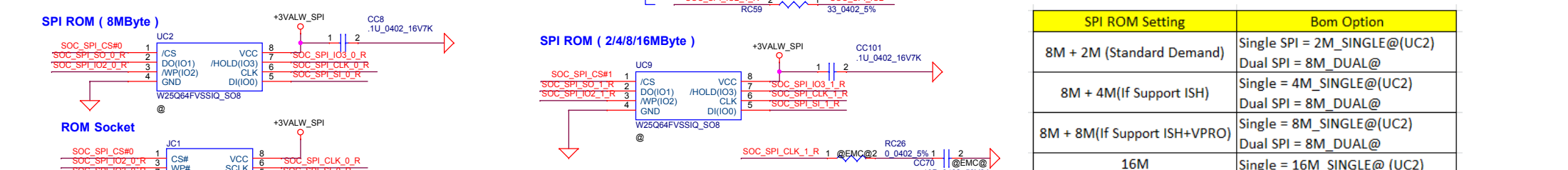
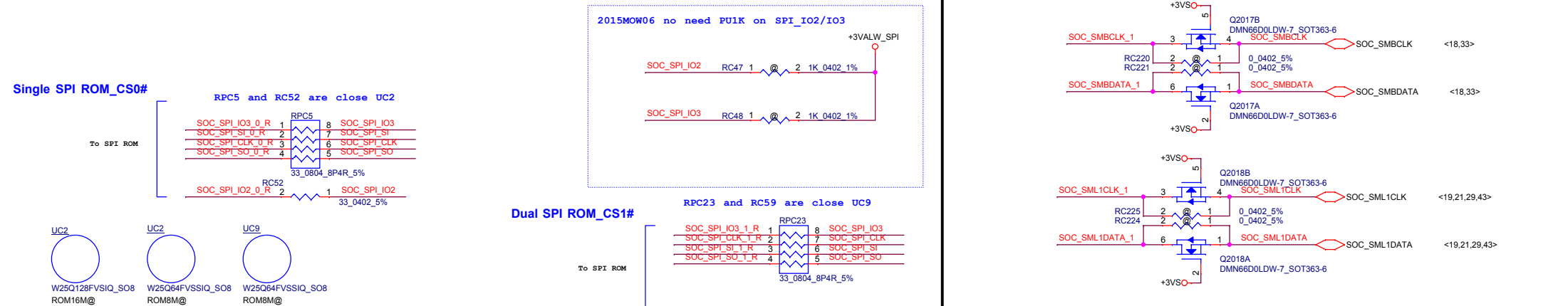
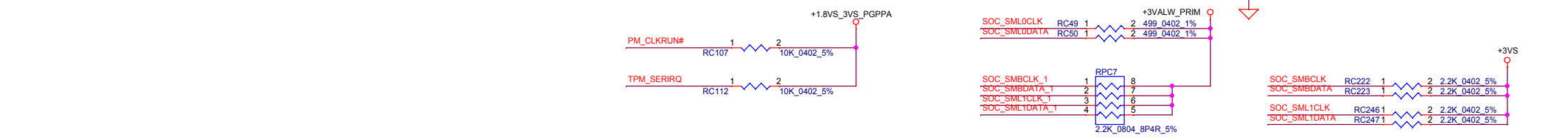
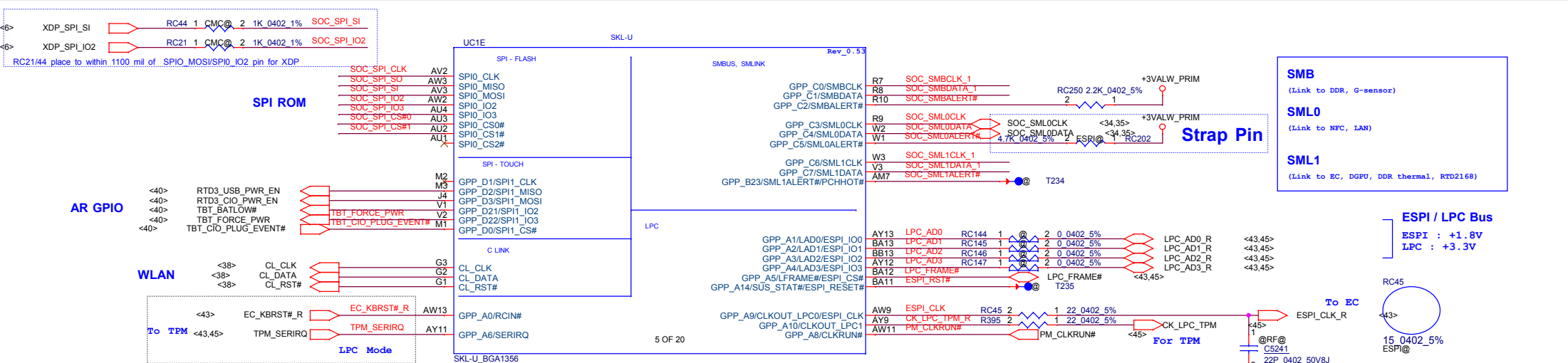
RC196 2 1 51 0.402% 5% SOC_XDP_TDO

RC197 2 1 51 0.402% 5% SOC_XDP_TDO

Interleaved Memory



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SPI ROM Setting	Bom Option
8M + 2M (Standard Demand)	Single SPI = 2M_SINGLE@(UC2) Dual SPI = 8M_DUAL@
8M + 4M(If Support ISH)	Single = 4M_SINGLE@(UC2) Dual SPI = 8M_DUAL@
8M + 8M(If Support ISH+VPRO)	Single = 8M_SINGLE@(UC2) Dual SPI = 8M_DUAL@
16M	Single = 16M_SINGLE@ (UC2)

11.7.3 Intel HD Audio link capabilities

- Two SDI signals to support two external codecs.
- Drives variable frequency (6 MHz to 24 MHz) BCLK to support:
 - SDO double pumped up to 48 Mb/s
 - SDT's single pumped up to 24 Mb/s
- Provides cadence for 44.1 kHz-based sample rate output.
- Supports 1.5V, 1.8V and 3.3V modes.

Functional Strap Definitions

SPKR / GPP_B14 (Internal Pull Down):
(Sampled: Rising edge of PCH_PWROK)

TOP Swap Override
0 = Disable TOP Swap mode.----> AAX05 Use
1 = Enable TOP Swap Mode.

<37>

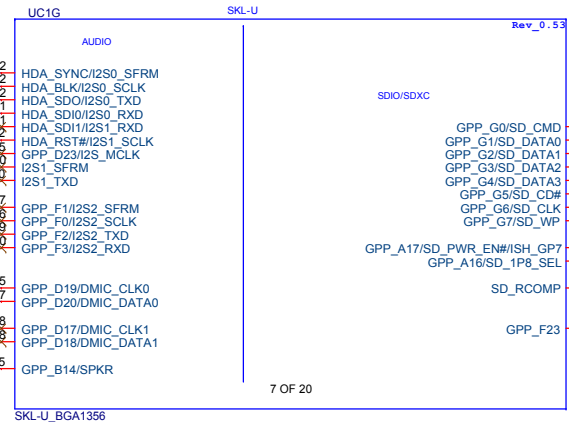
PCH_DMIC_CLK

PCH_DMIC_DATA

PCH_DMIC_CLK
PCH_DMIC_DATA

<37>

BEEP#



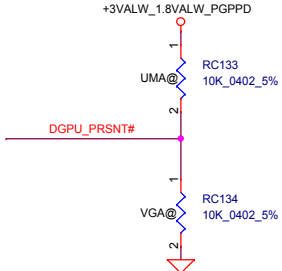
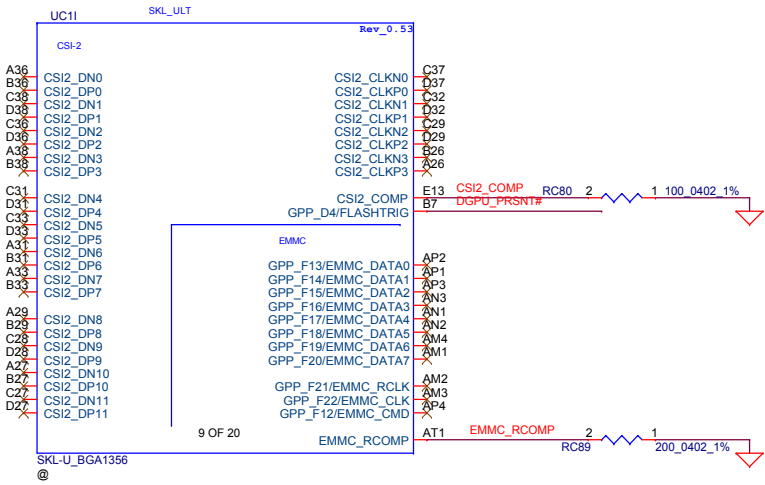
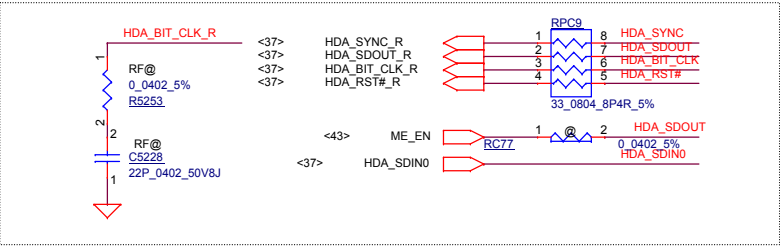
#543016 PDG0.9 P.321
Terminating Unused SD Q/S DMC S gnd's
SDIO signals are multiplexed with GPIO and default to GPIO functionality (as input). If SDIO interface is not used, the signals can be used as GPIOs instead. If the GPIO functionality is also not used the signals can be left as non-connect

62.3.38 RCOMP Checklist

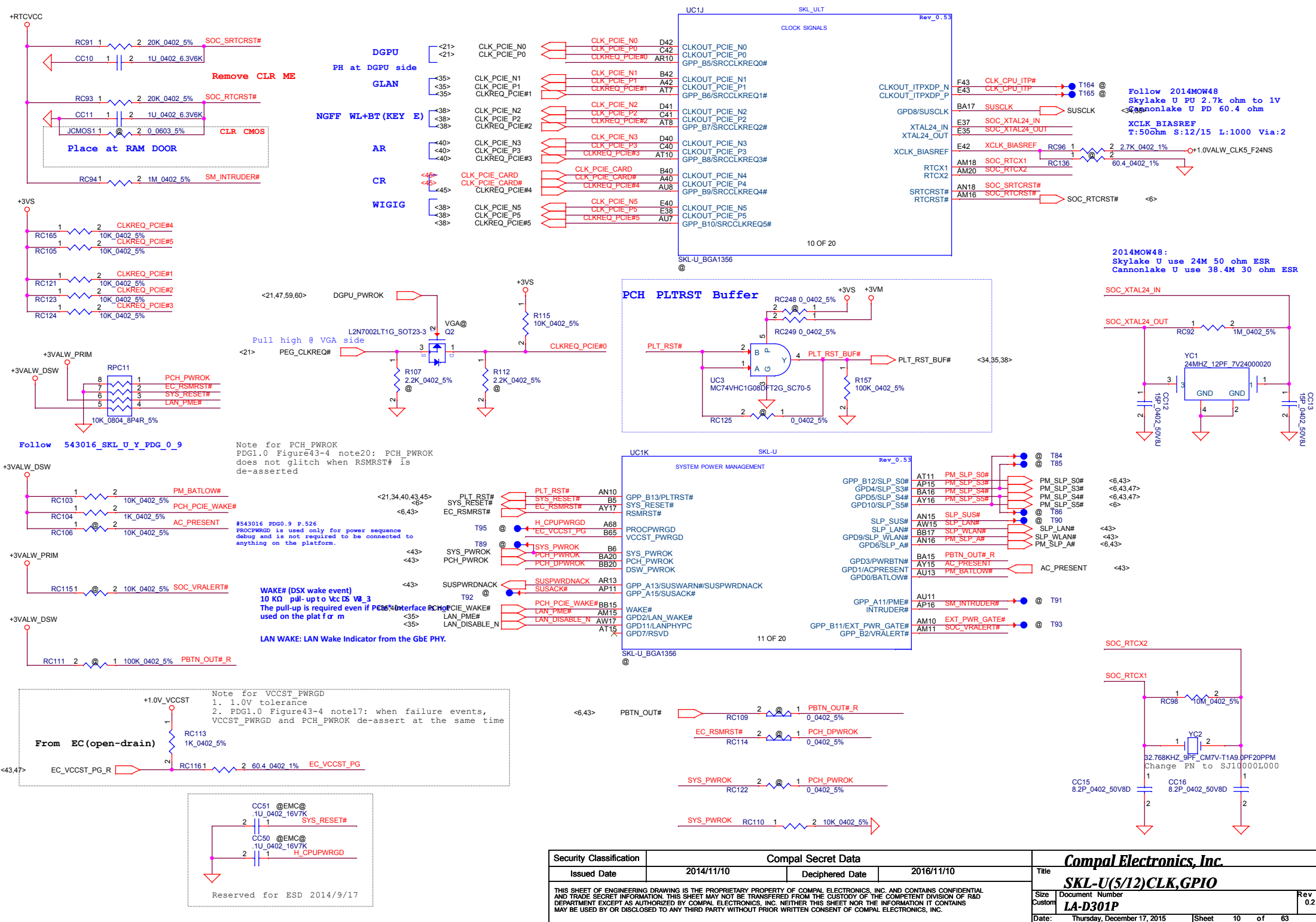
Table 62-48. RCOMP Checklist

Component	Value	✓
NOA_RCOMP	49.9 ohm +/- 1% pull down termination to GND	
FEQ_COMP	24.9ohm +/- 1% pull down termination to GND	
SD_RCOMP	200ohms termination to GND	
EMMC_RCOMP	200ohms termination to GND	
PCIE_RCOMP[0]	100 ohm +/- 1%. Differential between RCOMP[0]/RCOMP[1]	
USM2_COMP	113 Ohm +/- 1% differential termination to GND; DC resistance <0.5ohm.	
SD_RCOMP	200ohms termination to GND	
EMMC_RCOMP	200ohms termination to GND	
PCH_POPRCOMP	DC resistance <0.2ohm. 49.9 ohm termination resistor to GND.	
PCIE_RCOMP[0]	100 ohm +/- 1%. Differential between RCOMP[0]/RCOMP[1]	
CSI2_COMP	100 ohm +/- 1% termination resistor to GND; DC resistance <0.5ohm.	
USM2_COMP	113 Ohm +/- 1% differential termination to GND; DC resistance <0.5ohm.	

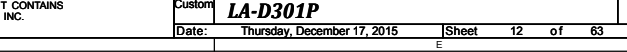
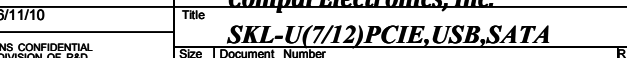
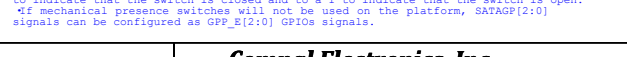
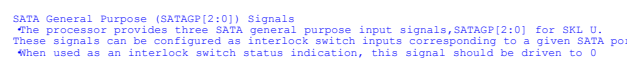
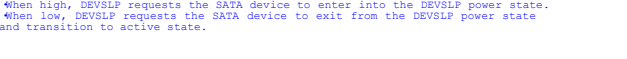
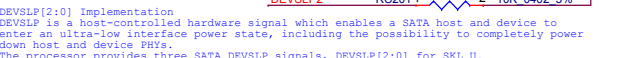
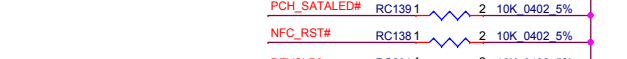
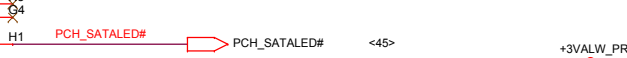
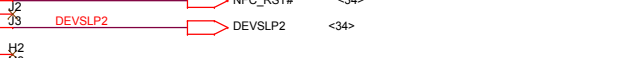
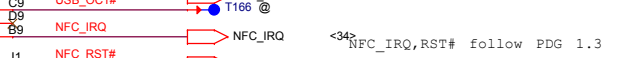
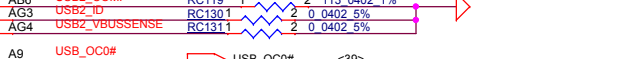
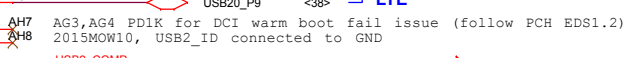
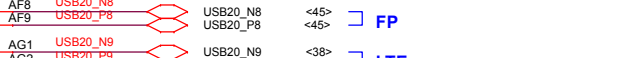
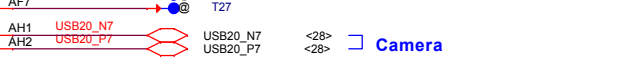
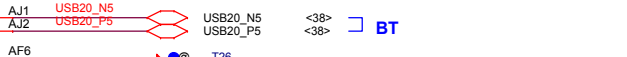
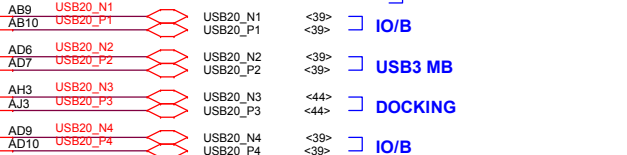
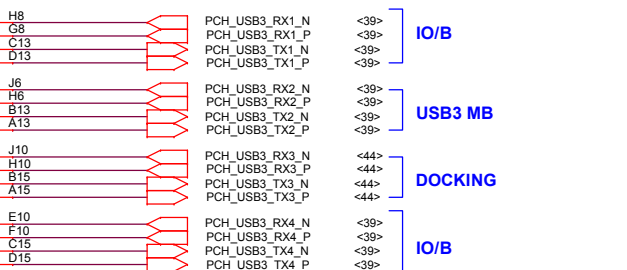
HDA for AUDIO



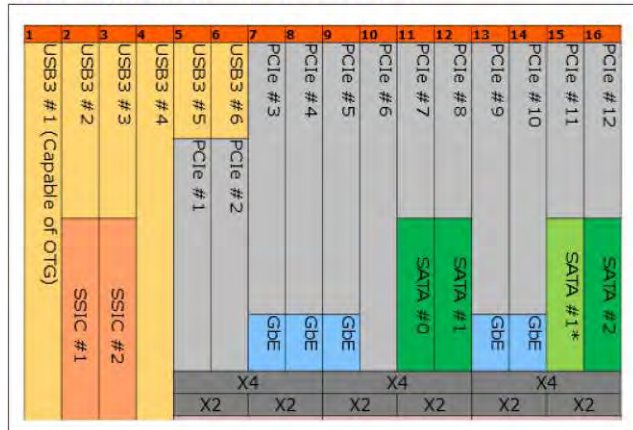
	GPIO67 DGPU_PRSN#
DIS, Optimus	0
UMA	1



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High Speed I/O (HSIO) Lane Multiplexing in SKL U



Acer HSIO def i ne



GPIO	DEVICE CONTROL
USB_OC0#	USB2 Port 1,2,4
USB_OC1#	NA
USB_OC2#	NA
USB_OC3#	NA
DEVSLP0	NA
DEVSLP1	SSD
DEVSLP2	NA
SATA_GP0	NA
SATA_GP1	NA
SATA_GP2	NA

DEVSLP[2:0] Implementation

DEVSLP is a host-controlled hardware signal which enables a SATA host and device to enter an ultra-low-power state, including the possibility to completely power down host and device PHYs.

The processor provides three SATA DEVSLP signals, DEVSLP[2:0] for SKL U.

When high, DEVSLP requests the SATA device to enter into the DEVSLP power state.

DEVSLP requests the SATA device to exit from the DEVSLP power state and transition to active state.

SATA General Purpose (SATAGP[2:0]) Signals

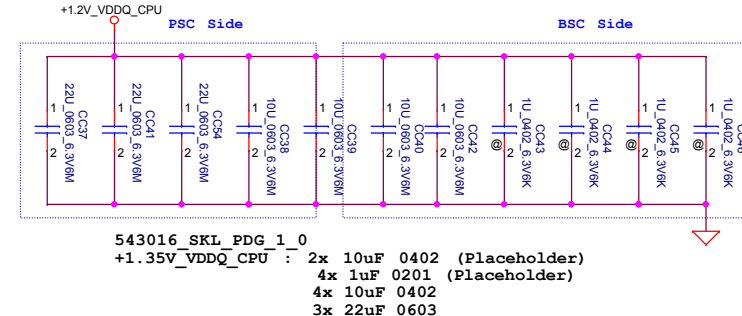
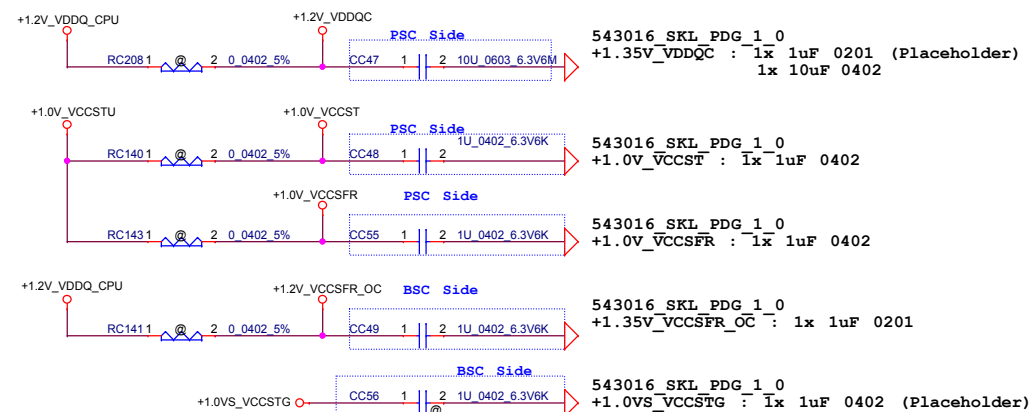
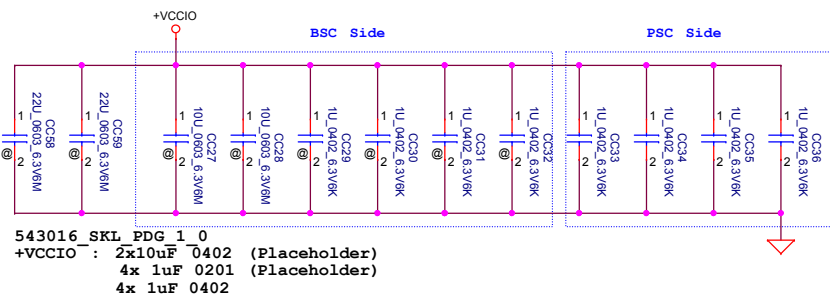
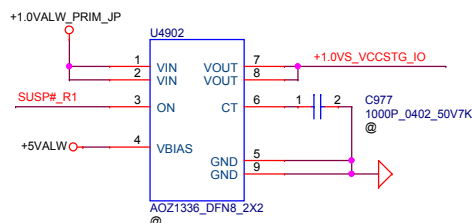
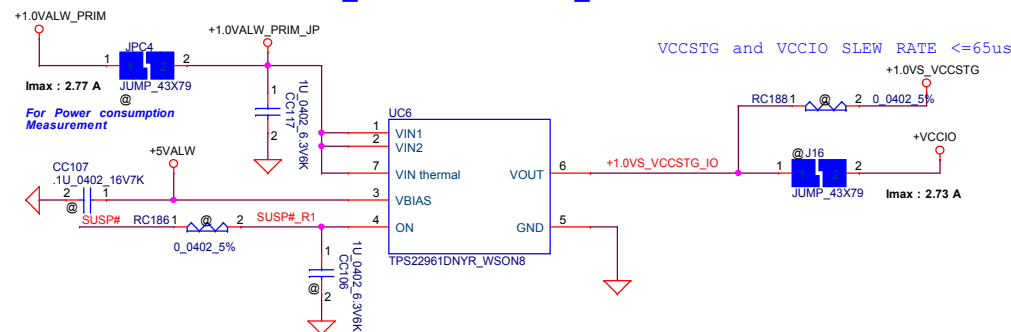
- The processor provides three SATA general purpose input signals, SATAGP[2:0] for SKL U. These signals can be configured as interlock switch inputs corresponding to a given SATA port.
- When used as an interlock switch status indication, this signal should be driven to 0 to indicate that the switch is closed and to a 1 to indicate that the switch is open.
- When used as a presence switch, the signal should be used on the platform, SATAGP[2:0] signals can be configured as GPE E[2:0] GPEOS signals.

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				Custom	LA-D301P	0.2
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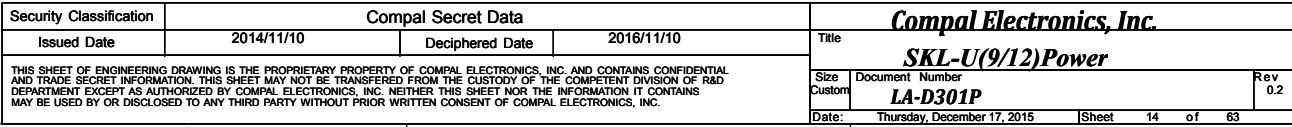
The schematic diagram illustrates the power management section for the UC5 chip. The chip is connected to several power rails and components:

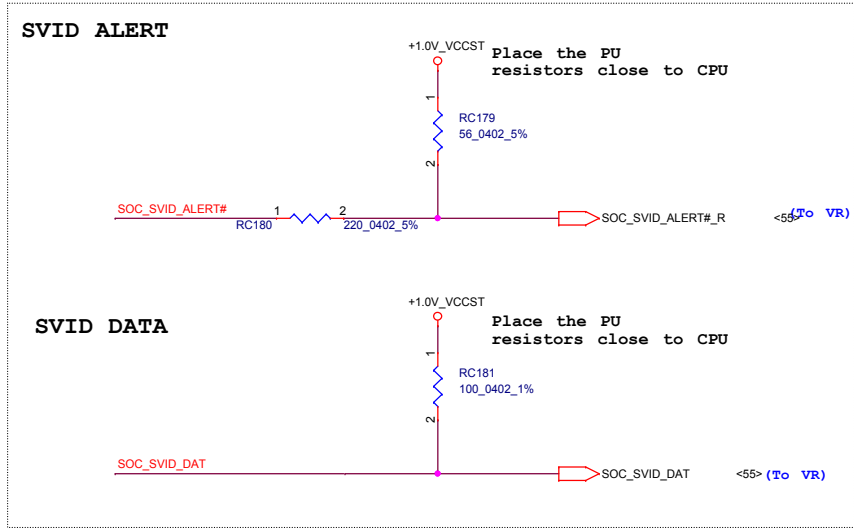
- UC5 Pin Connections:**
 - Pins 1 and 2: VIN1
 - Pins 3 and 4: EN_1.0V_VCCSTU
 - Pins 5 and 6: VBIAS
 - Pins 7 and 8: VIN2
 - Pins 9 and 10: VOUT2
 - Pins 11 and 12: GND
 - Pins 13 and 14: VOUT1
 - Pins 15 and 16: GPAD
- Power Rails and Components:**
 - +5VALW:** Connected to pin 1 via capacitor CC98.
 - +1.0VALW_PRIM:** Connected to pin 2 via capacitor CC97.
 - +1.0V_VCCSTU:** Connected to pin 3 via capacitor CC96.
 - +1.8VALW_VS:** Connected to pin 5 via capacitor CC105.
 - +1.8VALW_PRIM:** Connected to pin 6 via capacitor CC104.
 - +1.8V:** Connected to pin 9 via capacitor CC95.
 - +1.0V_VCCSTU:** Connected to pin 11 via capacitor CC94.
 - +1.8V:** Connected to pin 13 via capacitor CC100.
- Other Components:**
 - Resistors: RC142 (20K), RC1681 (20K).
 - Capacitors: CC105, CC104, CC98, CC97, CC96, CC95, CC94, CC100.
 - Inductors: JPC8, JPC9.

A large blue text overlay at the bottom right reads: **+1.8VALW_PRIM TO +1.8VS**.



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Issued Date	2014/11/10	Deciphered Date	2016/11/10	Title SKL-U(8/12)Power		
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Note: [1] Does not apply when rails are merged.

To minimize any stray noise pickup to the Vcc_SENSE/Vss_SENSE lines

- Sense traces should be referenced to a solid ground plane
- Avoid crossing over plane splits
- Maintain a 25-mil separation distance away from any other dynamic signals

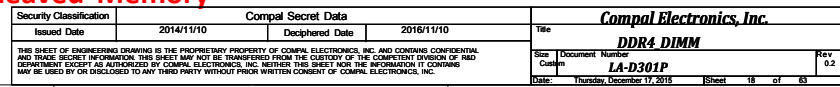
543016 PDG0.9 P.189 Need check

Table 10-10.SVID Bus Routing Guidelines

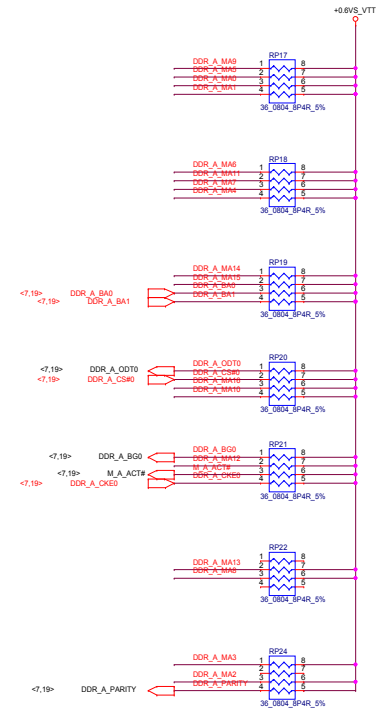
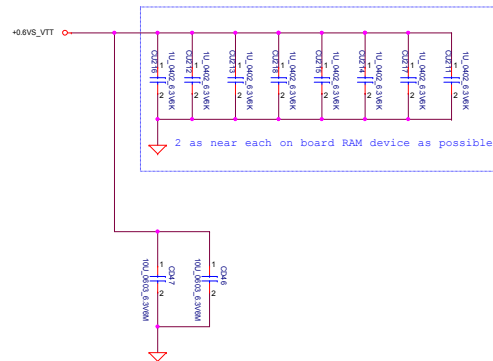
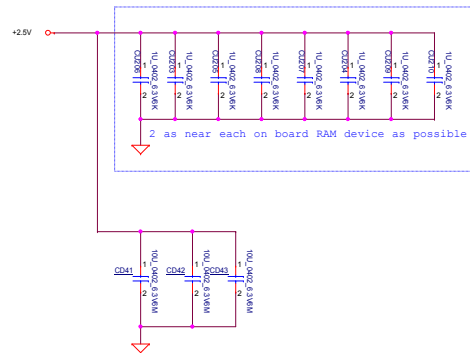
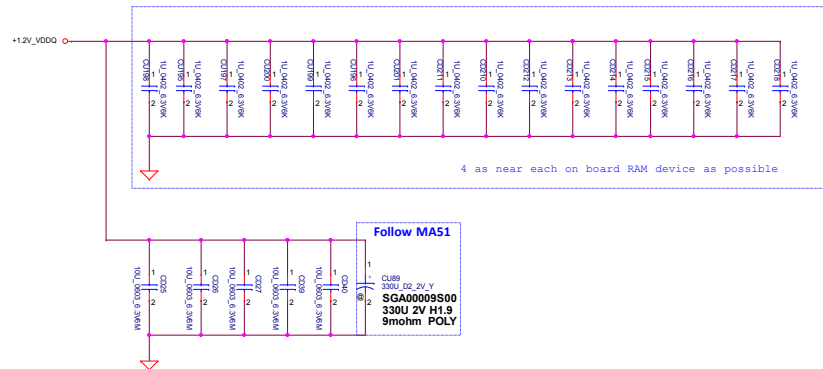
Signal	W1 [inches s]	W2 [inches s]	W3/ 4/5 [inches s]	W2+W3+W4+W5 [inches]	W51 [inches s]	W52 [inches s]	R _{PU1} [Ω]	R _{PU2} [Ω]	R _{S1} [Ω]	R _{S2} [Ω]	VCC st [V]
VDSOUT							Empty	45	0	50	
VDSCK	0.5-3	1-15	0.5-4	3-17	<0.1	<0.1	100	100	0	10	1.0
VIDALER T#							56	Empty	220	0	

Power Rail	Description	Control
V _{CC}	Processor IA Cores Power Rail	SVID
V _{CCGT}	Processor Graphics Power Rails	SVID
V _{CCGTx}	Processor Graphics Extended Power Rail Available only for GT3/GT4 processor SKUs	SVID
V _{CCSA}	System Agent Power Rail	SVID (Fixed SKU dependent)
V _{QIO}	IO Power Rail	Fixed
V _{CCST}	Sustain Power Rail	Fixed
V _{CCPLL}	Processor PLLs power rail	Fixed
V _{DDQ}	Integrated Memory Controller Power Rail	Fixed (Memory technology dependent)
V _{CCGDC}	Processor DPC power rail (available only in SKUs with DPC)	Fixed
V _{CCGDC_199}	Processor DPC power rail (available only in SKUs with DPC)	Fixed
V _{CCOPDIO}	Processor EOPDIO power rail (available only in SKUs with OPC)	Fixed

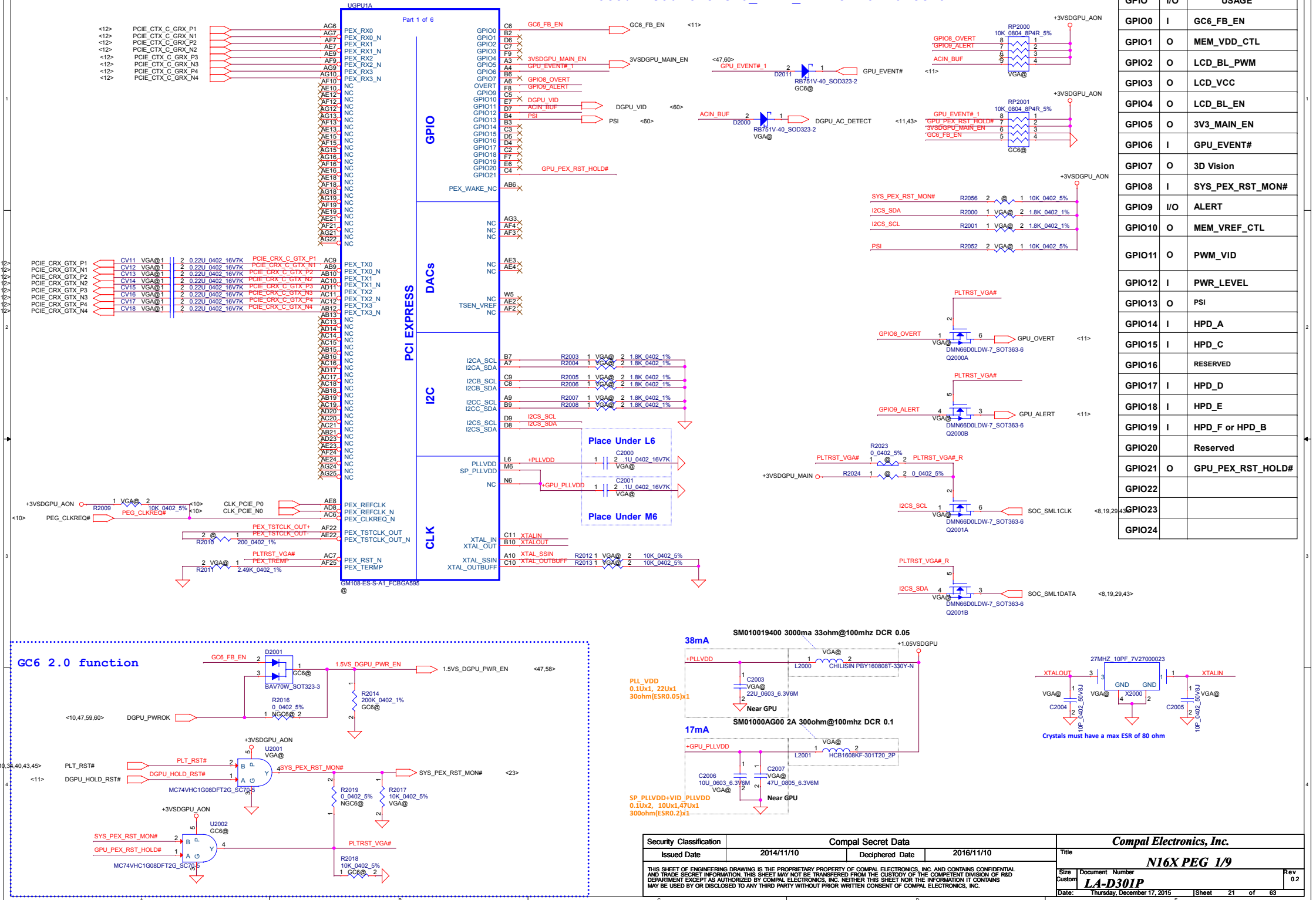
UC1P SKL-U Rev_0.53			UC1Q SKL-U Rev_0.53			UC1R SKL-U Rev_0.53		
GND 1 OF 3			GND 2 OF 3			GND 3 OF 3		
A5	VSS	AL65	AT63	VSS	BA49	F8	VSS	L18
A67	VSS	AL66	AT68	VSS	BA53	G10	VSS	L2
A70	VSS	AM13	AT71	VSS	BA57	G22	VSS	L20
AA2	VSS	AM21	AU10	VSS	BA6	G43	VSS	L4
AA4	VSS	AM25	AU15	VSS	BA62	G45	VSS	L8
AA65	VSS	AM27	AU20	VSS	BA66	G48	VSS	N10
AA68	VSS	AM43	AU32	VSS	BA71	G5	VSS	N13
AB15	VSS	AM45	AU38	VSS	BB18	G52	VSS	N19
AB16	VSS	AM46	AV1	VSS	BB26	G55	VSS	N21
AB18	VSS	AM55	AV68	VSS	BB30	G58	VSS	N6
AB21	VSS	AM60	AV69	VSS	BB34	G6	VSS	N65
AB8	VSS	AM61	AV70	VSS	BB38	G60	VSS	N68
AD13	VSS	AM68	AV71	VSS	BB43	G63	VSS	P17
AD16	VSS	AM71	AW10	VSS	BB55	G66	VSS	P19
AD19	VSS	AM8	AW12	VSS	BB6	H15	VSS	P20
AD20	VSS	AN20	AW14	VSS	BB60	H18	VSS	P21
AD21	VSS	AN23	AW16	VSS	BB64	H71	VSS	R13
AD62	VSS	AN28	AW18	VSS	BB67	J11	VSS	R6
AD8	VSS	AN30	AW21	VSS	BB70	J13	VSS	T15
AE64	VSS	AN32	AW23	VSS	C1	J25	VSS	T17
AE65	VSS	AN33	AW26	VSS	C25	J28	VSS	T18
AE66	VSS	AN35	AW28	VSS	C5	J32	VSS	T2
AE67	VSS	AN37	AW30	VSS	D10	J35	VSS	T21
AE68	VSS	AN38	AW32	VSS	D11	J38	VSS	T4
AE69	VSS	AN40	AW34	VSS	D14	J42	VSS	U10
AF1	VSS	AN42	AW36	VSS	D18	J8	VSS	U63
AF10	VSS	AN58	AW38	VSS	D22	K16	VSS	U64
AF15	VSS	AN63	AW41	VSS	D25	K18	VSS	U66
AF17	VSS	AP10	AW43	VSS	D26	K22	VSS	U67
AF2	VSS	AP18	AW45	VSS	D30	K61	VSS	U69
AF4	VSS	AP20	AW47	VSS	D34	K63	VSS	U70
AF63	VSS	AP23	AW49	VSS	D39	K64	VSS	V16
AG16	VSS	AP28	AW51	VSS	D44	K65	VSS	V17
AG17	VSS	AP32	AW53	VSS	D45	K66	VSS	V18
AG18	VSS	AP35	AW55	VSS	D47	K67	VSS	W13
AG19	VSS	AP38	AW57	VSS	D48	K68	VSS	W6
AG20	VSS	AP42	AW6	VSS	D53	K70	VSS	W9
AG21	VSS	AP58	AW60	VSS	D58	K71	VSS	Y17
AG71	VSS	AP63	AW62	VSS	D6	L11	VSS	Y19
AH13	VSS	AP68	AW64	VSS	D62	L16	VSS	Y20
AH6	VSS	AP70	AW66	VSS	D66	L17	VSS	Y21
AH63	VSS	AR11	AW8	VSS	D69			
AH64	VSS	AR15	AY66	VSS	E11			
AH67	VSS	AR16	B10	VSS	E15			
AJ15	VSS	AR20	B14	VSS	E18			
AJ18	VSS	AR23	B18	VSS	E21			
AJ20	VSS	AR28	B22	VSS	E46			
AJ4	VSS	AR35	B30	VSS	E50			
AK11	VSS	AR42	B34	VSS	E53			
AK16	VSS	AR43	B39	VSS	E56			
AK18	VSS	AR45	B44	VSS	E6			
AK21	VSS	AR46	B48	VSS	E65			
AK22	VSS	AR48	B53	VSS	E71			
AK27	VSS	AR5	B58	VSS	F1			
AK63	VSS	AR50	B62	VSS	F13			
AK68	VSS	AR52	B66	VSS	F2			
AK69	VSS	AR53	B71	VSS	F22			
AK8	VSS	AR55	BA1	VSS	F23			
AL2	VSS	AR58	BA10	VSS	F27			
AL28	VSS	AR63	BA14	VSS	F28			
AL32	VSS	AR8	BA18	VSS	F32			
AL35	VSS	AT2	BA2	VSS	F33			
AL38	VSS	AT20	BA23	VSS	F35			
AL4	VSS	AT23	BA28	VSS	F37			
AL45	VSS	AT28	BA32	VSS	F38			
AL48	VSS	AT35	BA36	VSS	F4			
AL52	VSS	AT4	F68	VSS	F40			
AL55	VSS	AT42	BA45	VSS	F42			
AL58	VSS	AT56		VSS	BA41			
AL64	VSS	AT58		VSS				
16 OF 20			17 OF 20			18 OF 20		
SKL-U_BGA1356			SKL-U_BGA1356			SKL-U_BGA1356		
@			@			@		



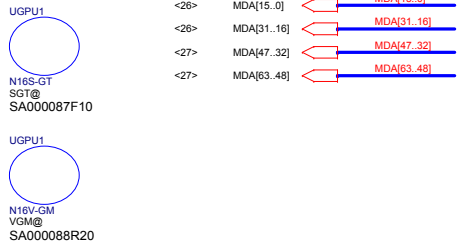
<7,19> DDR_A_MA[0..16]



Note: NGC6 3VSDGPU MAIN EN is no function



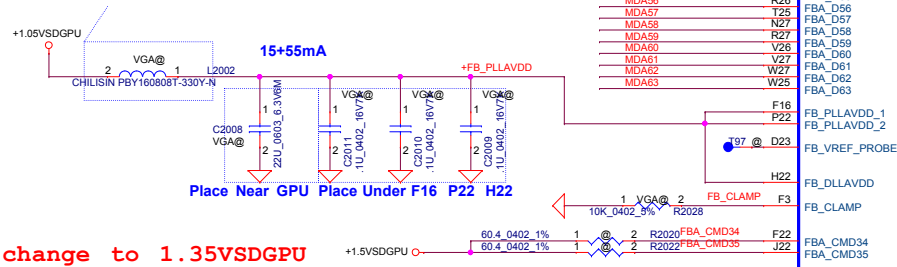
VRAM Interface



NV 15x DG-06803-V03

GPU Package	Rail	Capacitor Type	Footprint	Population	Location
GB2B-64	FBx_PLL_AVDD and FB_DLL_AVDD Combined	0.1 μ F	X7R	0402	2
		22 μ F	X5R	0805	1
		Bead Type			
		30 Ω (ESR=0.010 Ω)	0603	1	

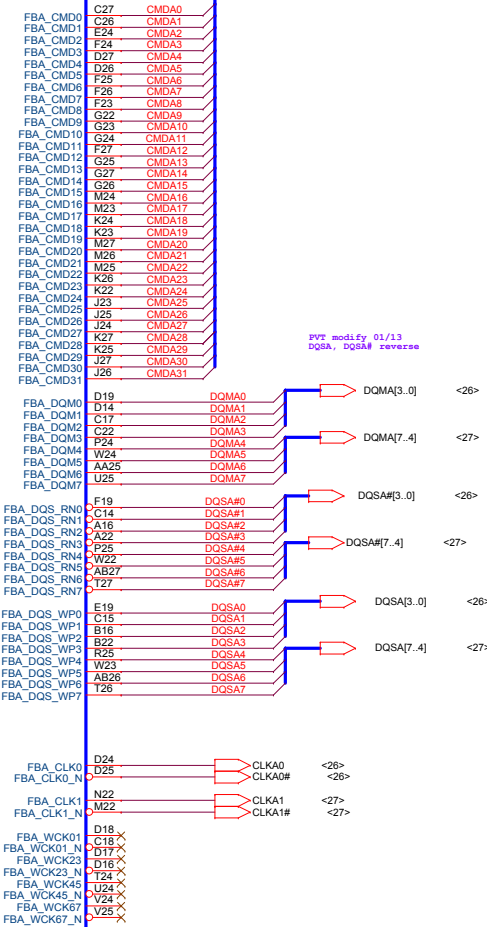
SM010019400 3000ma 33ohm@100mhz DCR 0.05



UGPU1B

Part 2 of 6

MEMORY INTERFACE A

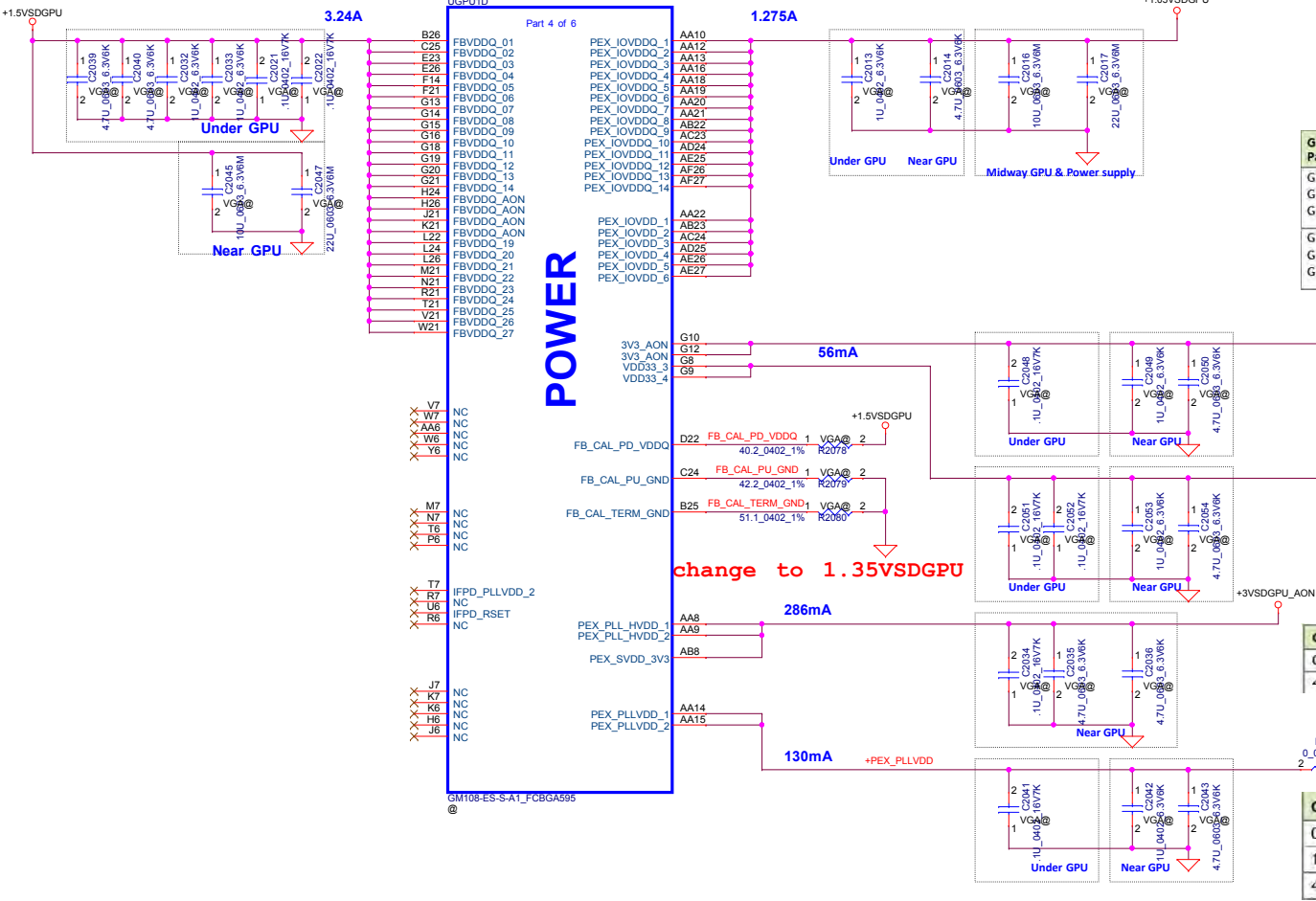


NV 15x DG-06803-V03

GPU Package Type	Capacitor Type		Footprint		Population	Location
GB2B-64 DDR3	0.1µF	X7R	0402	2	2	Under GPU
	1µF	X7R	0603	2	2	Under GPU
	4.7µF	X6S	0603	2	2	Under GPU
	10µF	X5R	0805	1	1	Near GPU
	22µF	X5R	0805	1	1	Near GPU

GPU Package Type	Capacitor Type		Footprint	Population	Location
GB2B-64	1.0 µF	X6S	0402	1	Under GPU
	4.7 µF	X6S	0603	1	Near GPU
	10 µF	X5R	0805	1	Midway between GPU and Power Supply
	22 µF	X5R	0805	1	Midway between GPU and Power Supply

change to 1.35VSDGPU



GPU Package	Rail	Capacitor Type		Footprint		Population	Location
GB2B-64	3V3_MAIN	0.1µF	X6S	0402	2	2	Under GPU
GB4B-128		1 µF	X5R	0603	1	1	Near GPU
GB3-256		4.7 µF	X5R	0603	1	1	Near GPU
GB2B-64	3V3_AON	0.1µF	X6S	0402	1	1	Under GPU
GB4B-128		1 µF	X5R	0603	1	1	Near GPU
GB3-256		4.7 µF	X5R	0603	1	1	Near GPU

Capacitor Type		Footprint	Population	Location
0.1 μF	X5R	0402	1	Near GPU
4.7 μF	X5R	0603	2	Near GPU

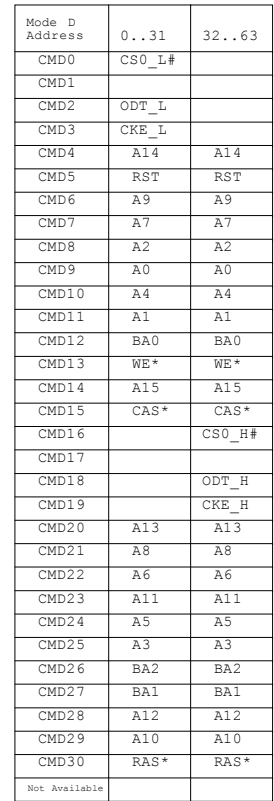
Capacitor Type		Footprint	Population	Location
0.1 µF	X6S	0402	1	Under GPU
1.0 µF	X5R	0603	1	Near GPU
4.7 µF	X5R	0805	1	Near GPU



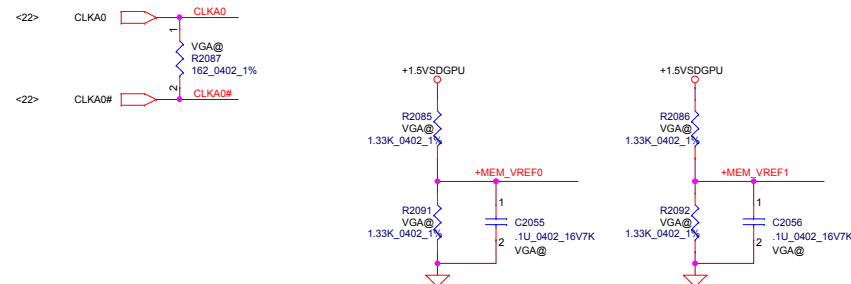
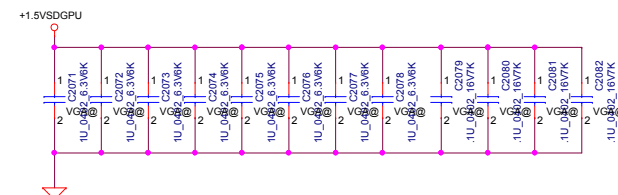
	N15V-GL
Power Supply Rail	DDR3
(V)	(A)
GPU Core Max.	28.26
FB Total	4.07
PEXVDD	1.82

Diagram illustrating the connection of the **QDSA** and **QDMA** modules to the **MDA** and **CMDA** modules:

- QDSA[7..0]** connects to **DQSA# [7..0]**.
- QDMA[7..0]** connects to **MDA[7..0]**.
- MDA[63..0]** connects to **CMDA[30..0]**.

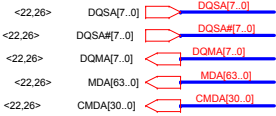


Capacitor Type			Population		Location
			FBVDDQ	FBVDD	
FBVDD/Q Combined					
0.1 μ F	X7R	0402	2		Under DRAM
1.0 μ F	X7R	0603	4		Under DRAM
10 μ F	X5R	0805	0		Close to DRAM

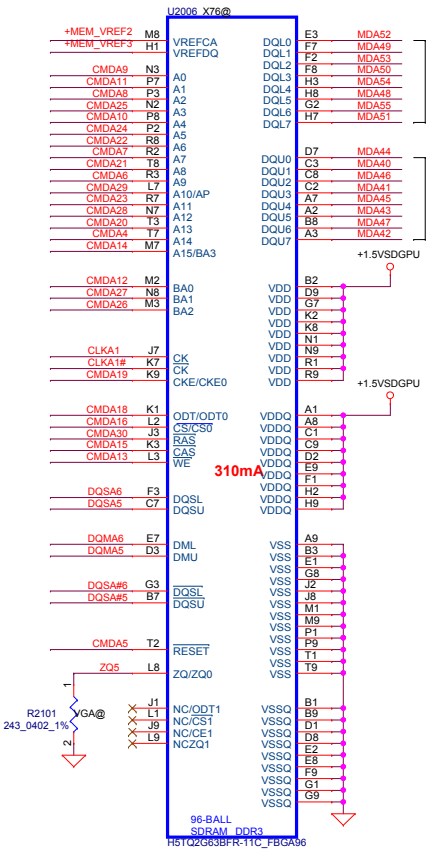
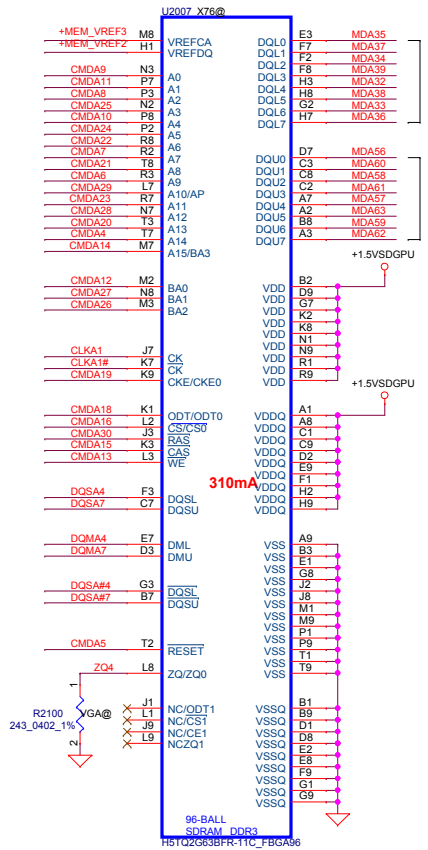


	Command Bit	Default Pull-down
DDR3	ODTx	10k
	CKEx	10k
	RST	10k
	CS*	No Termination

VRAM DDR3 chips



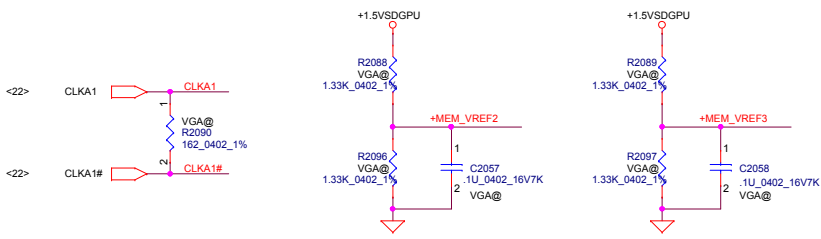
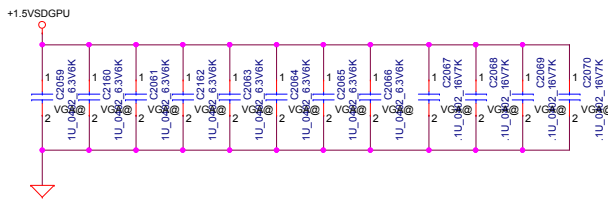
HIGH BIT

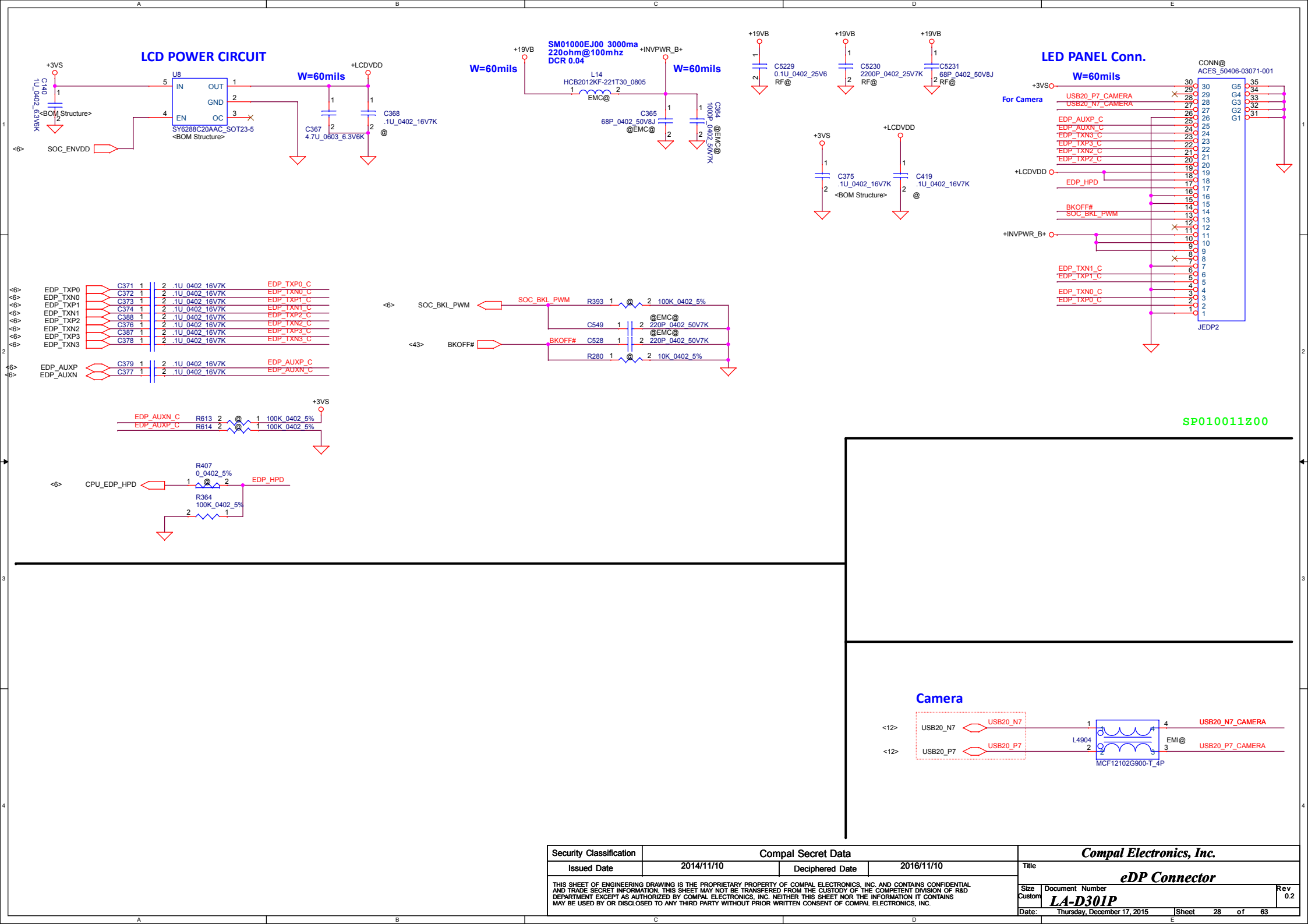


Mode D Address	0..31	32..63
CMD0	CS0_L#	
CMD1		
CMD2	ODT_L	
CMD3	CKE_L	
CMD4	A14	A14
CMD5	RST	RST
CMD6	A9	A9
CMD7	A7	A7
CMD8	A2	A2
CMD9	A0	A0
CMD10	A4	A4
CMD11	A1	A1
CMD12	BA0	BA0
CMD13	WE*	WE*
CMD14	A15	A15
CMD15	CAS*	CAS*
CMD16		CS0_H#
CMD17		
CMD18		ODT_H
CMD19		CKE_H
CMD20	A13	A13
CMD21	A8	A8
CMD22	A6	A6
CMD23	A11	A11
CMD24	A5	A5
CMD25	A3	A3
CMD26	BA2	BA2
CMD27	BA1	BA1
CMD28	A12	A12
CMD29	A10	A10
CMD30	RAS*	RAS*
Not Available		

LOW HIGH

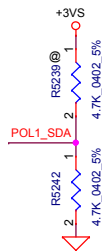
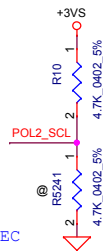
	Command Bit	Default Pull-down
DDR3	ODT*	10k
	CKE*	10k
	RST	10k
	CS*	No Termination



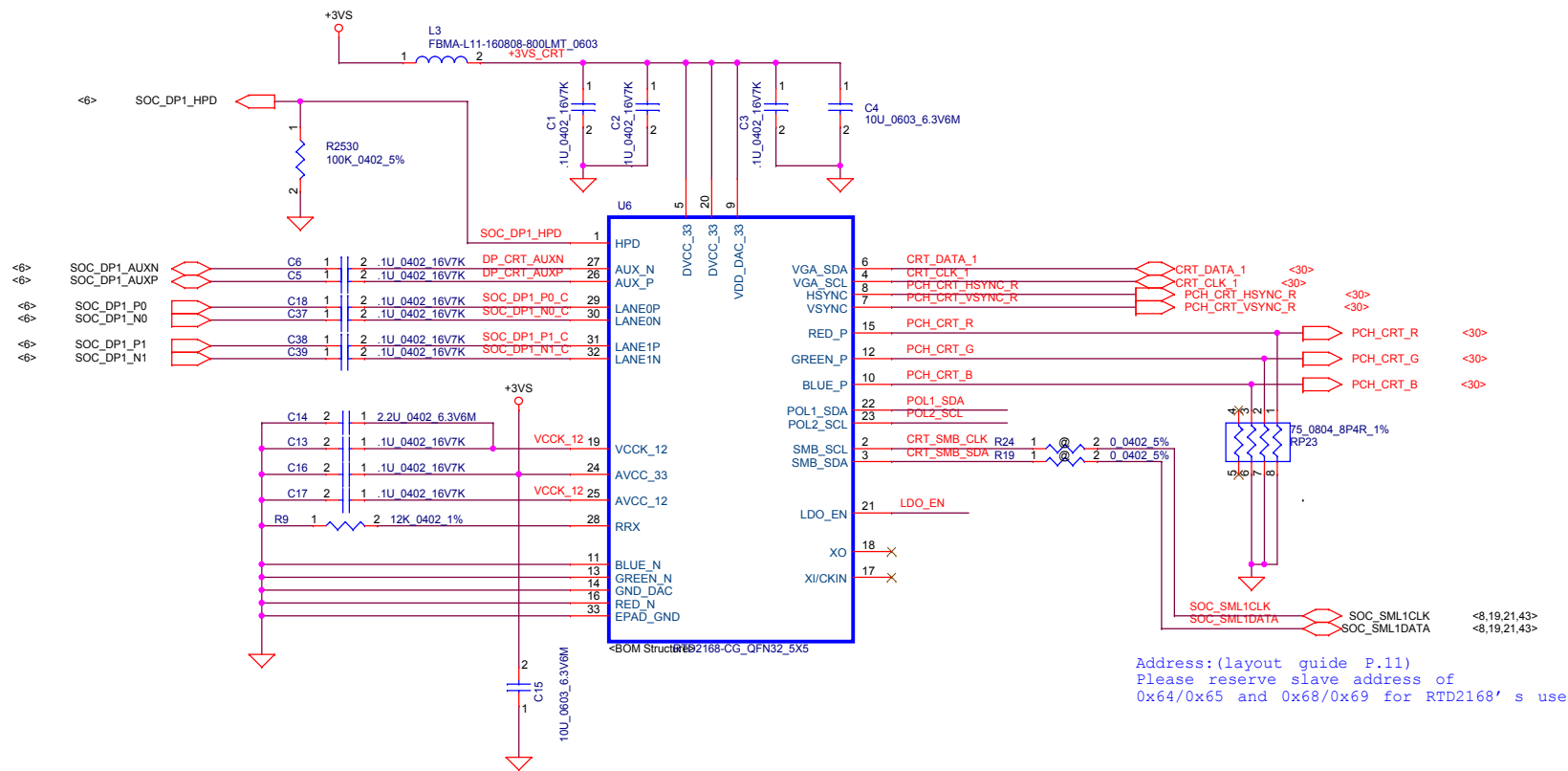


		POL_SDA	
		0	1
POL_SCL	0	X	EP
	1	*ROM	EEPROM

ROM: Internal ROM
EP: Programmed external EC
EEPROM: External ROM

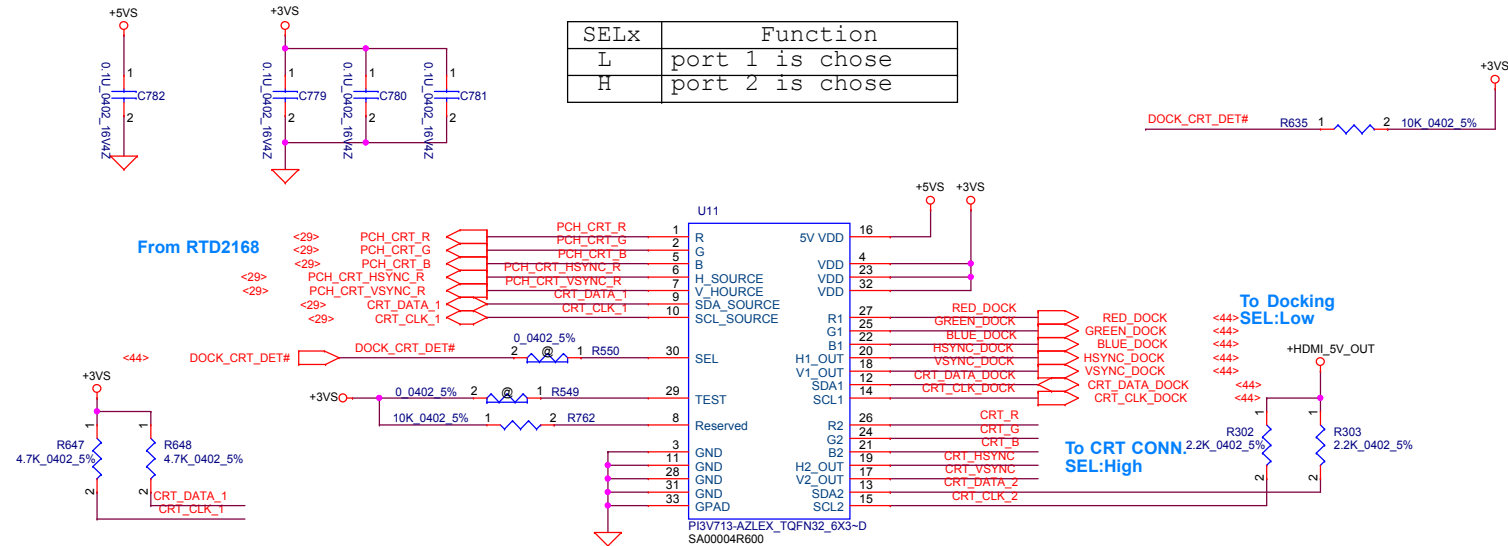
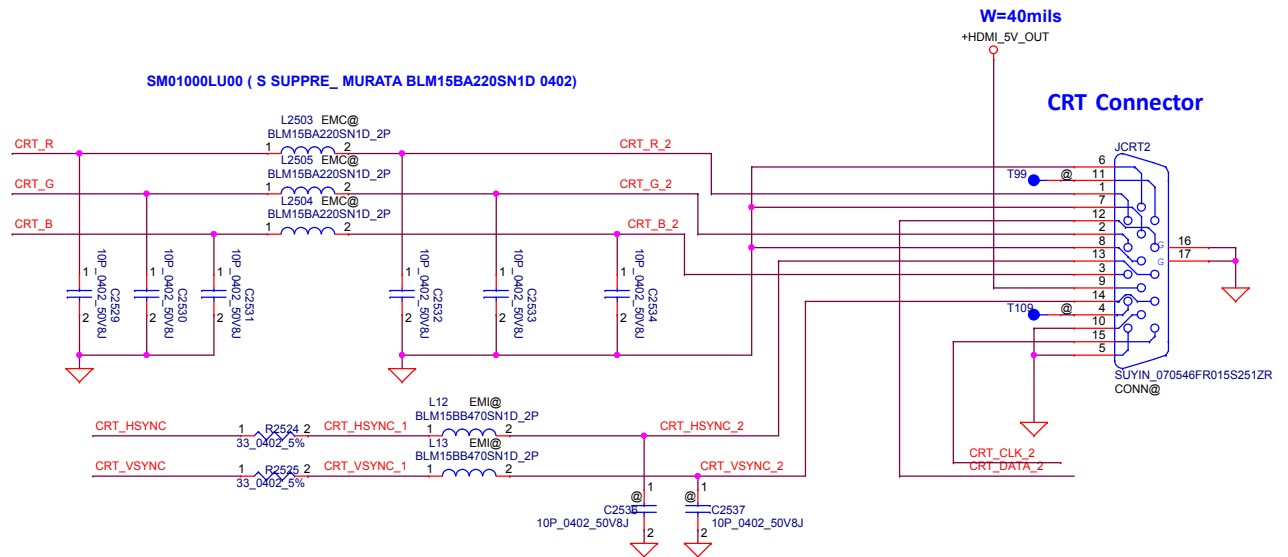


LDO EN:
*1: Internal 1.2V
0: External 1.2V



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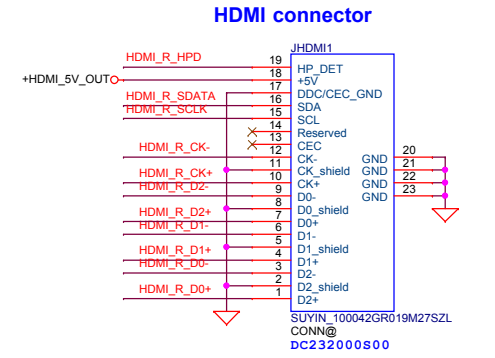
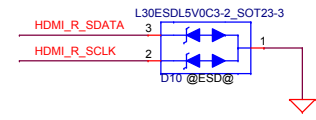
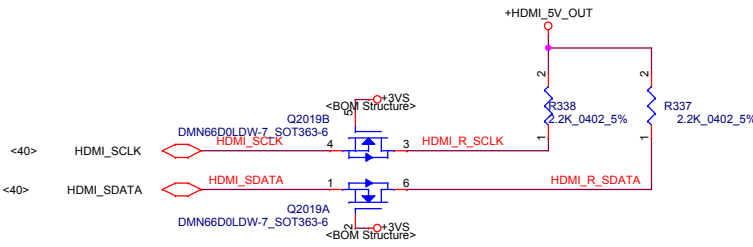
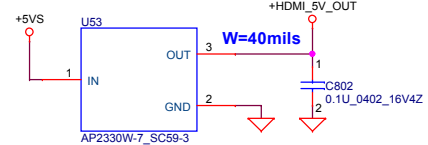
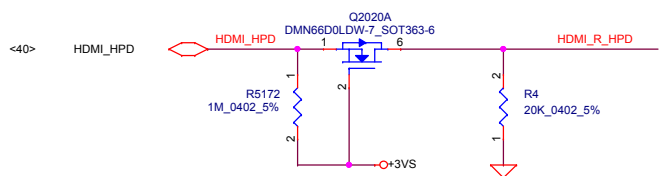
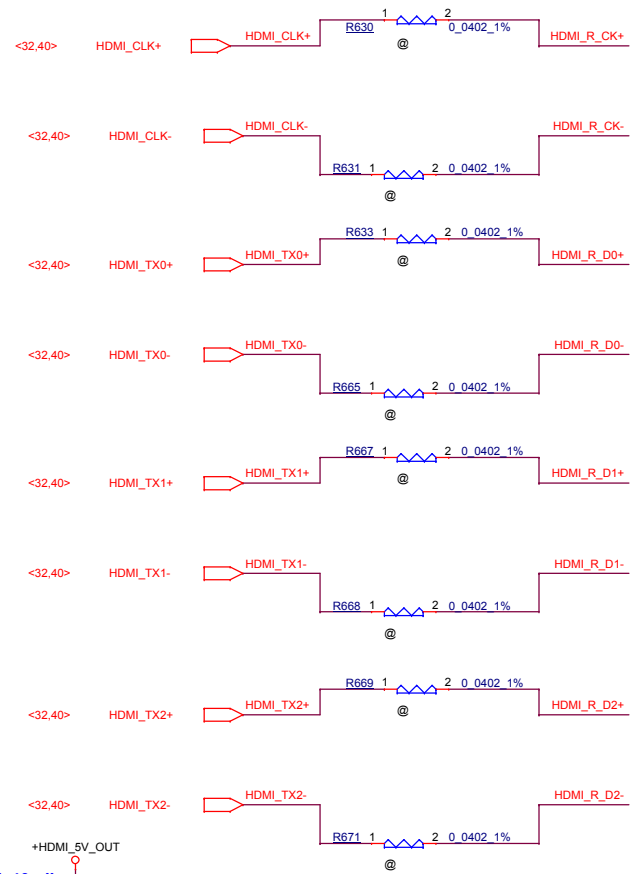
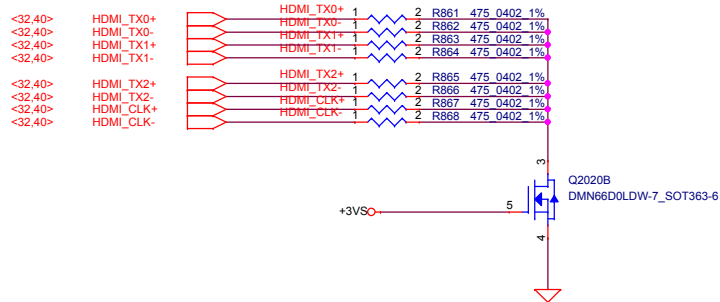
CRT conn.



SELx	Function
L	port 1 is chose
H	port 2 is chose

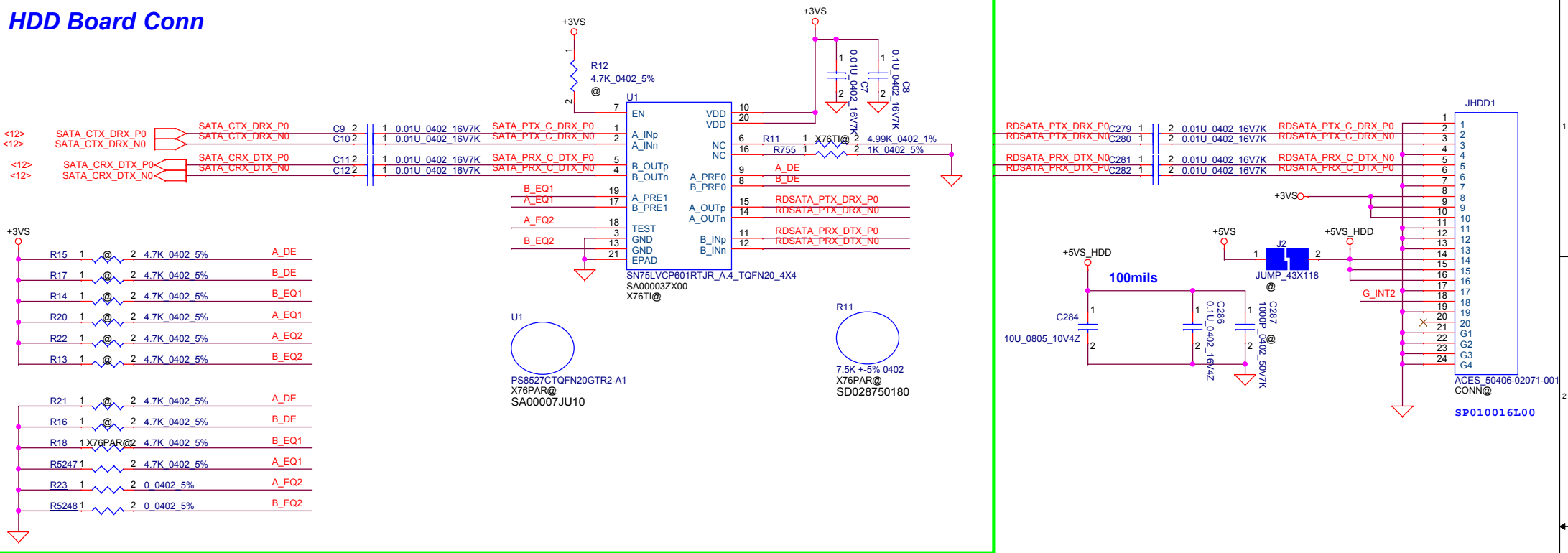
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the original BOM structure of R630, R631, R633, R665, R667, R668, R669, R671 is EMI@ , @ is for short pad only

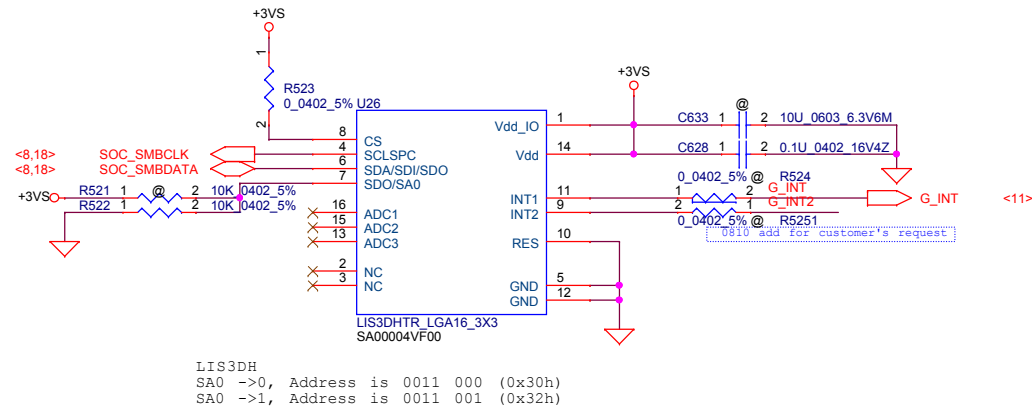


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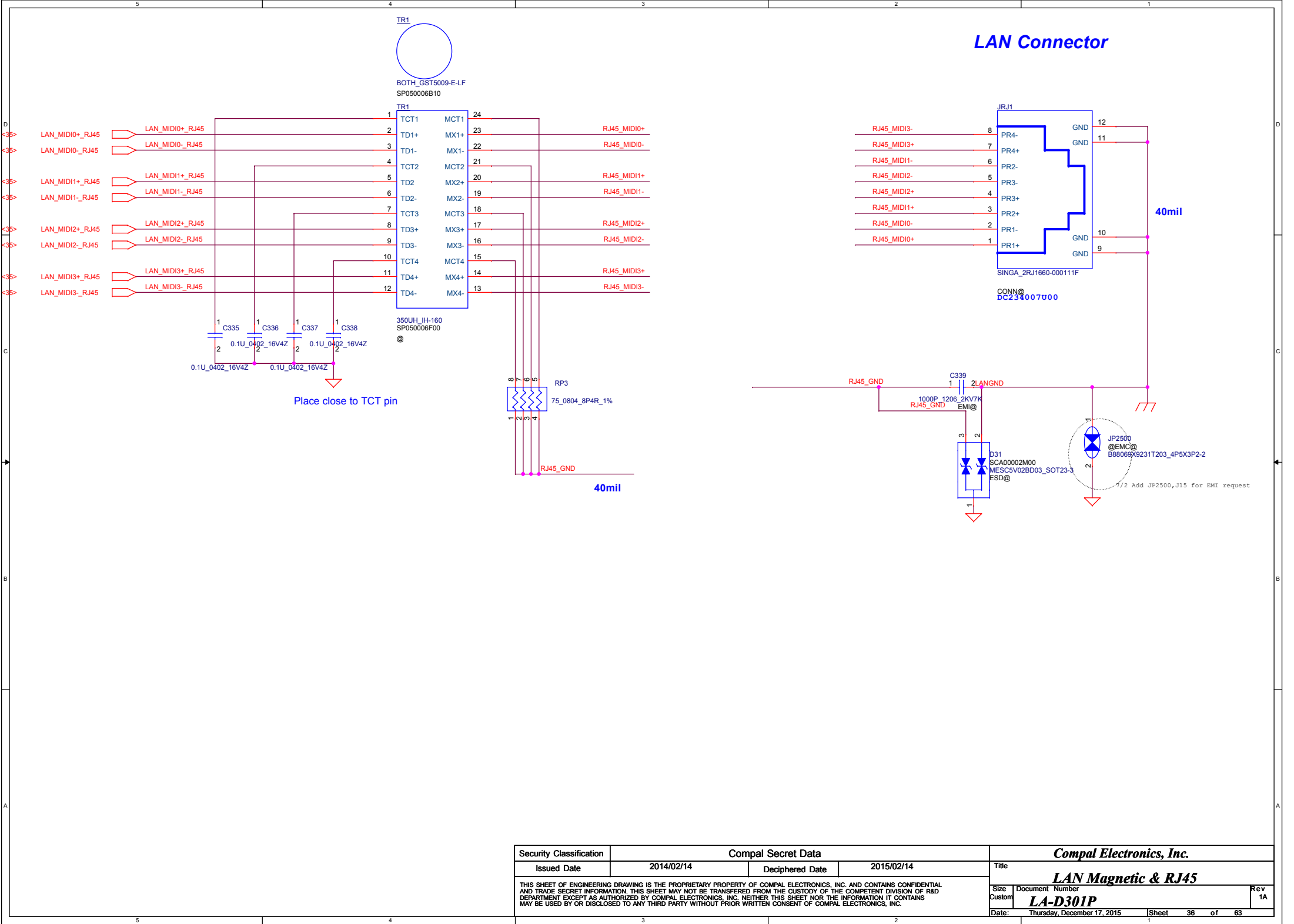
HDD Board Conn



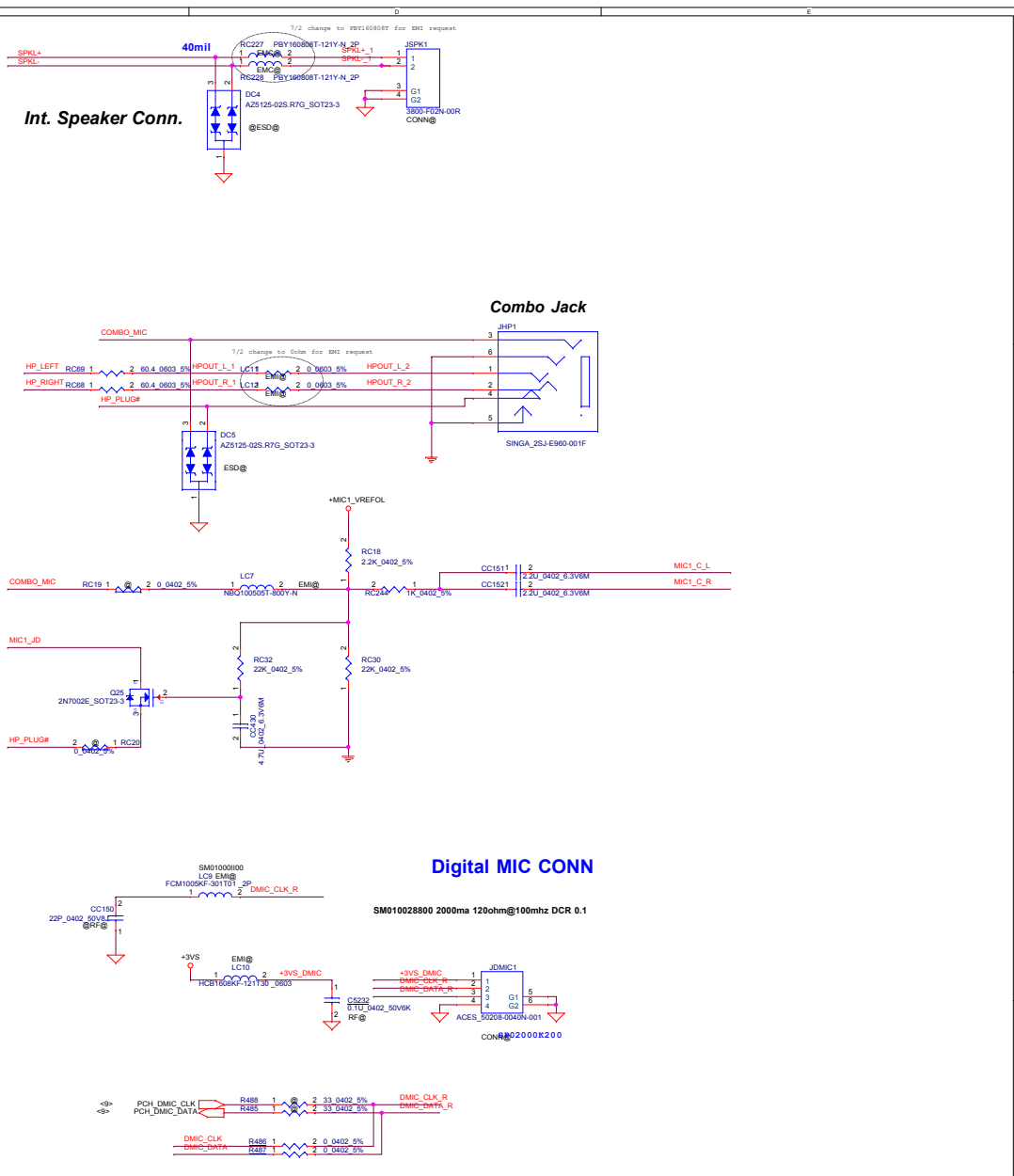
APS G-Sensor



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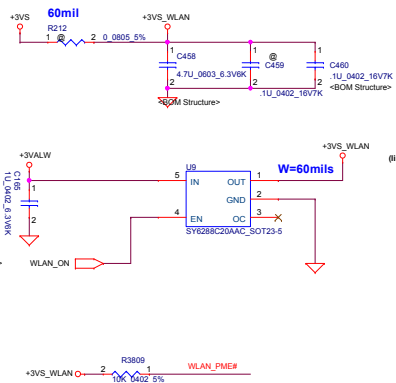


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Wireless LAN

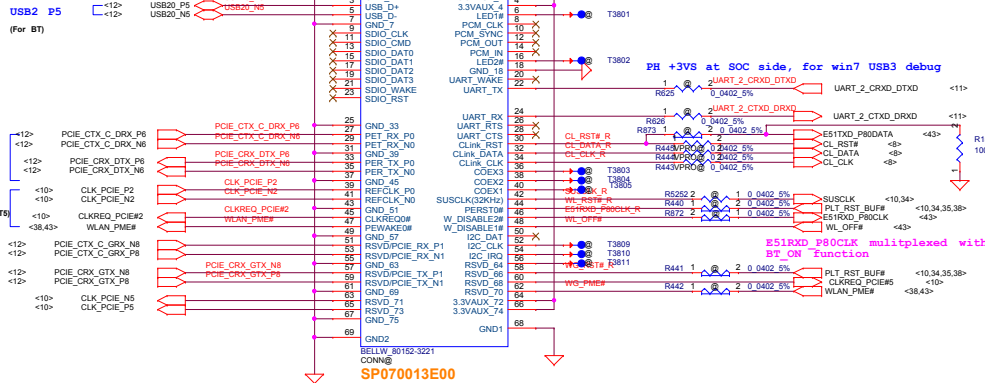


3.4.8.4.3.1.7.1. UART Wakeup

The UART power management protocol supports the following 4-wire and 5-wire interfaces:

- 4-Wire UART RXD (Input): Receive Data
- 4-Wire UART TXD (Output): Transmit Data
- 4-Wire RTS (Input): Request to Send (Host Flow Control)
- 4-Wire CTS (Output): Clear to Send (Device Flow Control)
- 5-Wire UART Wakeup (Output): Host wake-up line is optional in case the host support in band wake-up

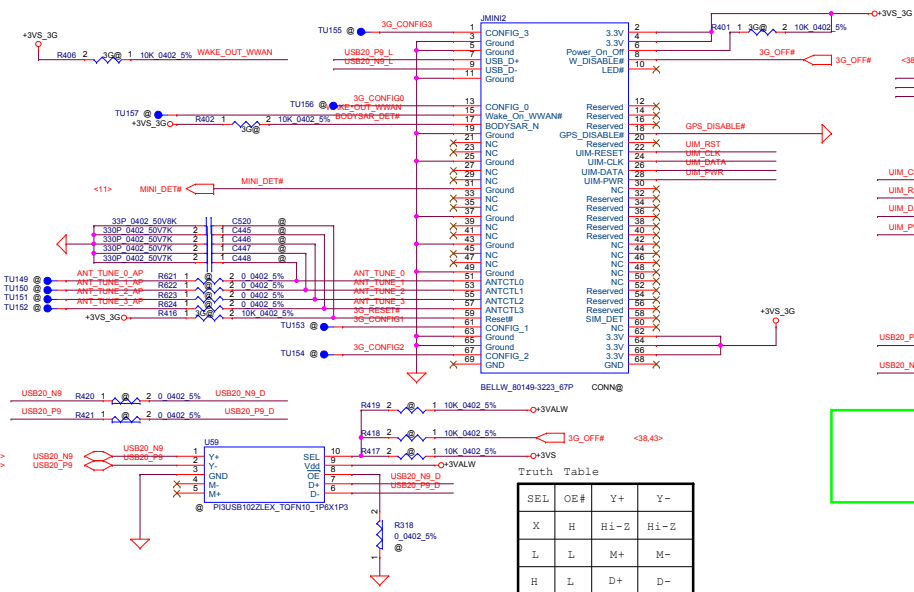
KEY E



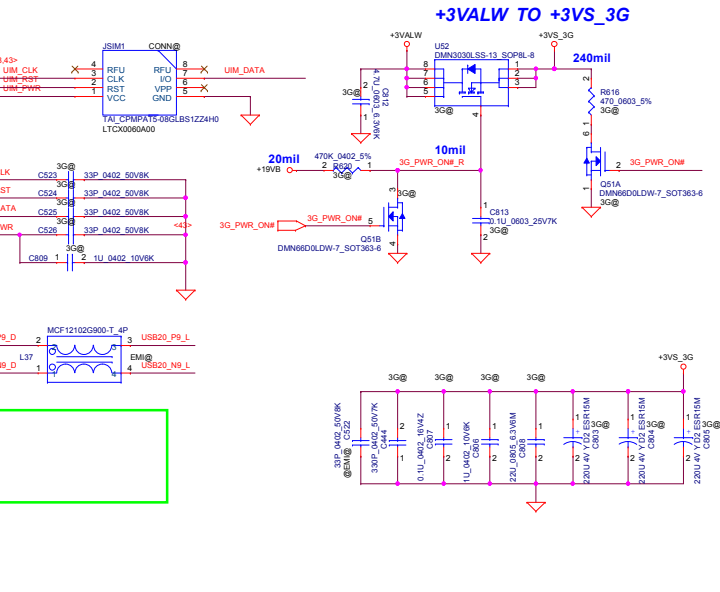
NGFF WL+BT+WIGIG (KEY E)

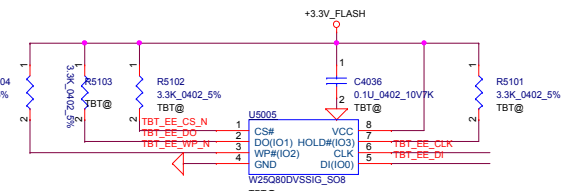
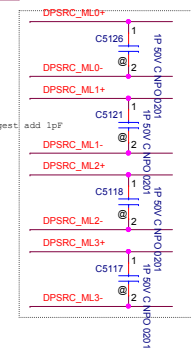
Wigig/WLAN/BT Combo Host Pin Configuration

Signal	Pin	Standard Definition	M.2 Connection	Standard Definition	Pin	WLAN
GND	1		GND		75	
VCC0_3V3	14	1.3V	REFCLKIN		73	TIME PE REFCLK
VCC0_3V3	15	1.3V	REFCLKP		71	TIME PE REFCLK
TIME PE LATCH	78	PERSTEN	GND		74	
TIME PE CLAREN	84	CLAREN	PERSTN		75	TIME PE REFCLK
TIME PE PERSTN	84	PERSTN	GND		76	
TIME PE	84	PERSTEN	GND		77	
TIME PE	84	PERSTEN	GND		78	
TIME PE	84	PERSTEN	GND		79	
TIME PE	84	PERSTEN	GND		80	
TIME PE	84	PERSTEN	GND		81	
TIME PE	84	PERSTEN	GND		82	
TIME PE	84	PERSTEN	GND		83	
TIME PE	84	PERSTEN	GND		84	
TIME PE	84	PERSTEN	GND		85	
TIME PE	84	PERSTEN	GND		86	
TIME PE	84	PERSTEN	GND		87	
TIME PE	84	PERSTEN	GND		88	
TIME PE	84	PERSTEN	GND		89	
TIME PE	84	PERSTEN	GND		90	
TIME PE	84	PERSTEN	GND		91	
TIME PE	84	PERSTEN	GND		92	
TIME PE	84	PERSTEN	GND		93	
TIME PE	84	PERSTEN	GND		94	
TIME PE	84	PERSTEN	GND		95	
TIME PE	84	PERSTEN	GND		96	
TIME PE	84	PERSTEN	GND		97	
TIME PE	84	PERSTEN	GND		98	
TIME PE	84	PERSTEN	GND		99	
TIME PE	84	PERSTEN	GND		100	



SEL	OE#	Y+	Y-
X	H	H1-Z	H1-Z
L	L	M+	M-
H	L	D+	D-





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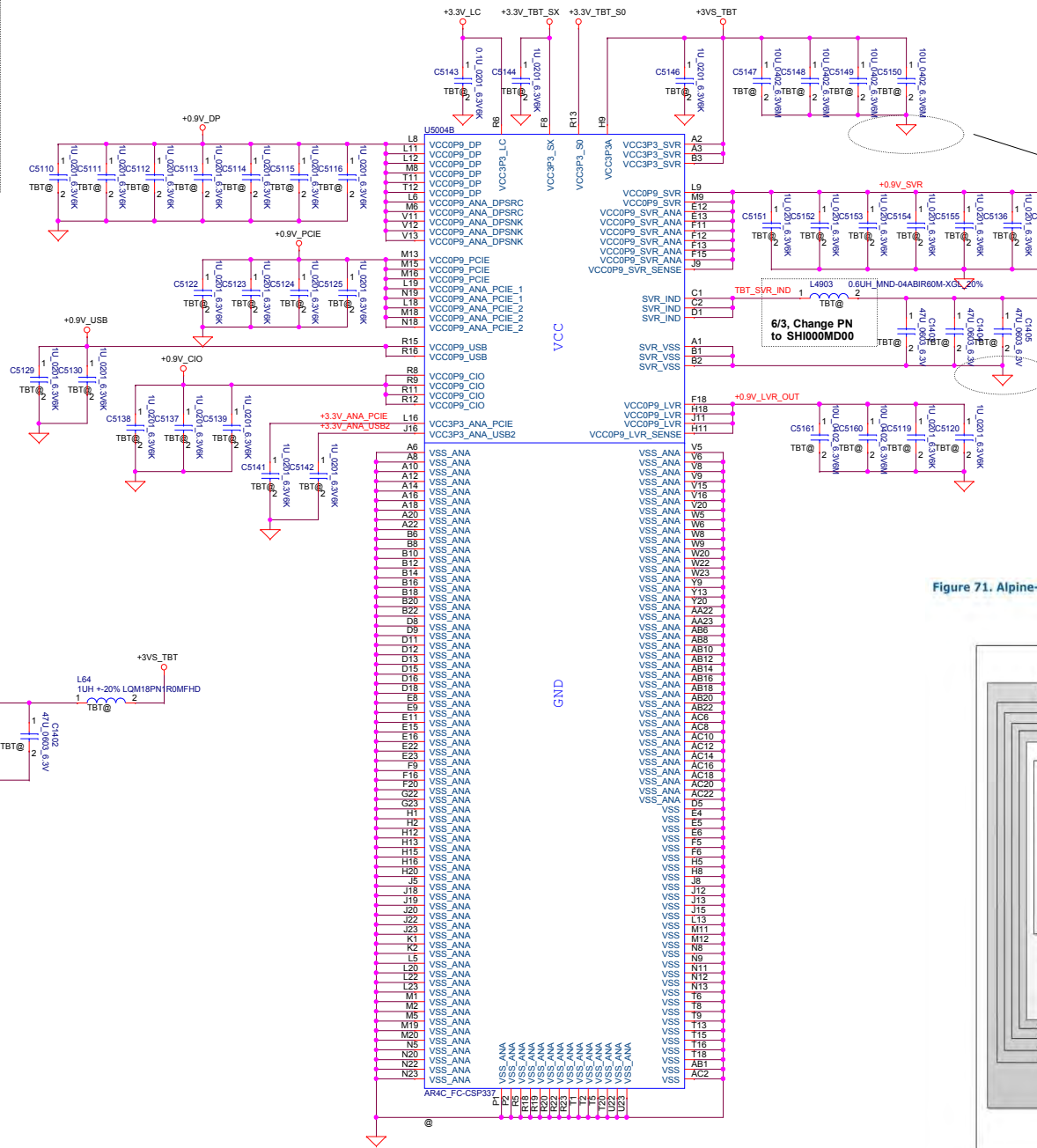
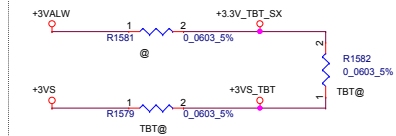
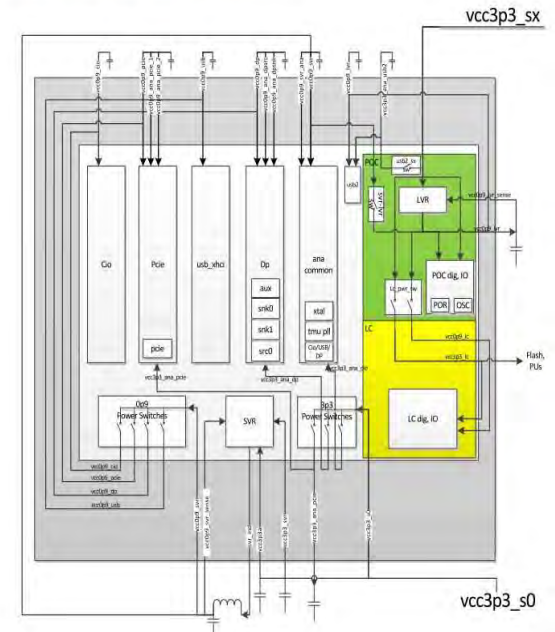
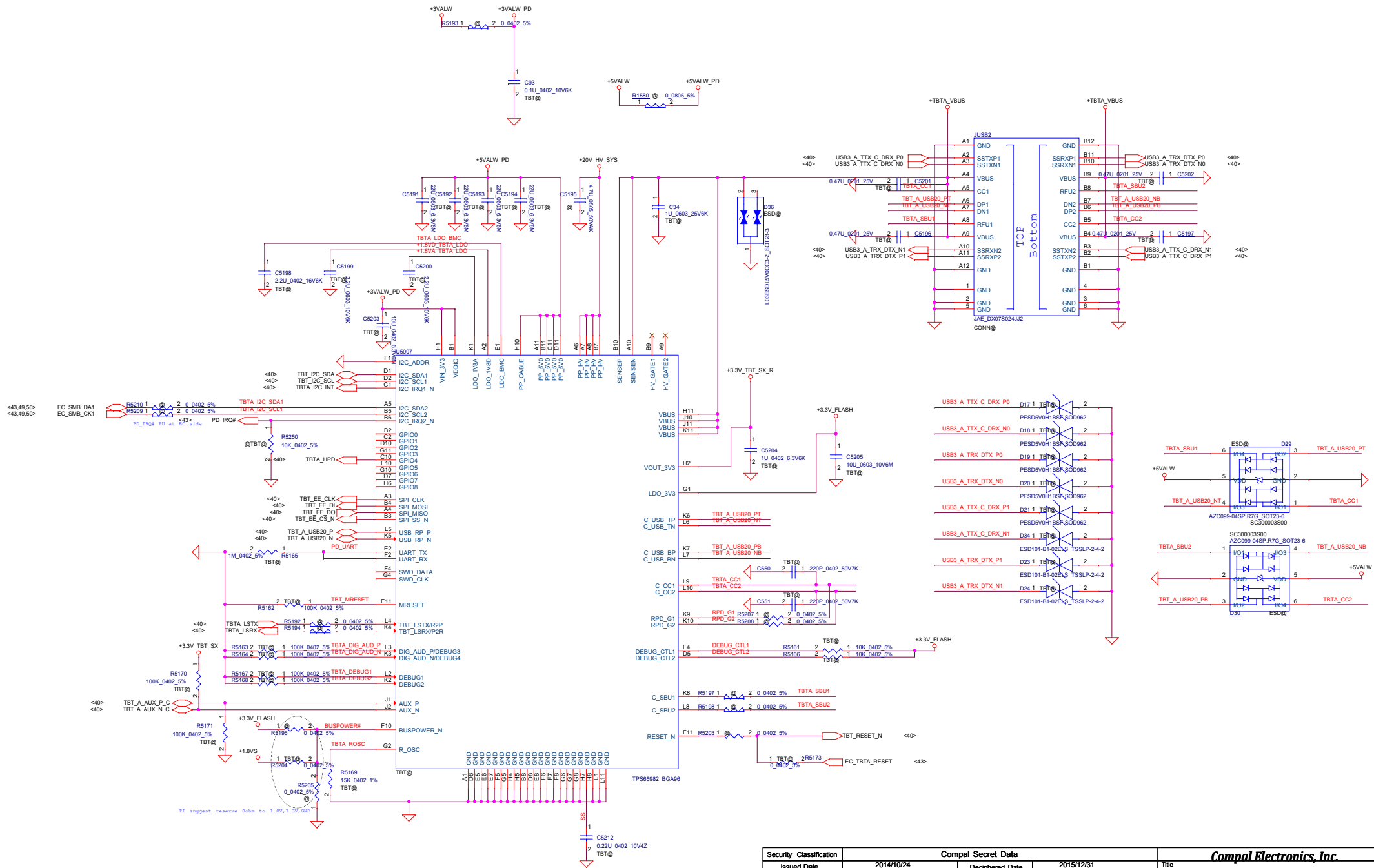
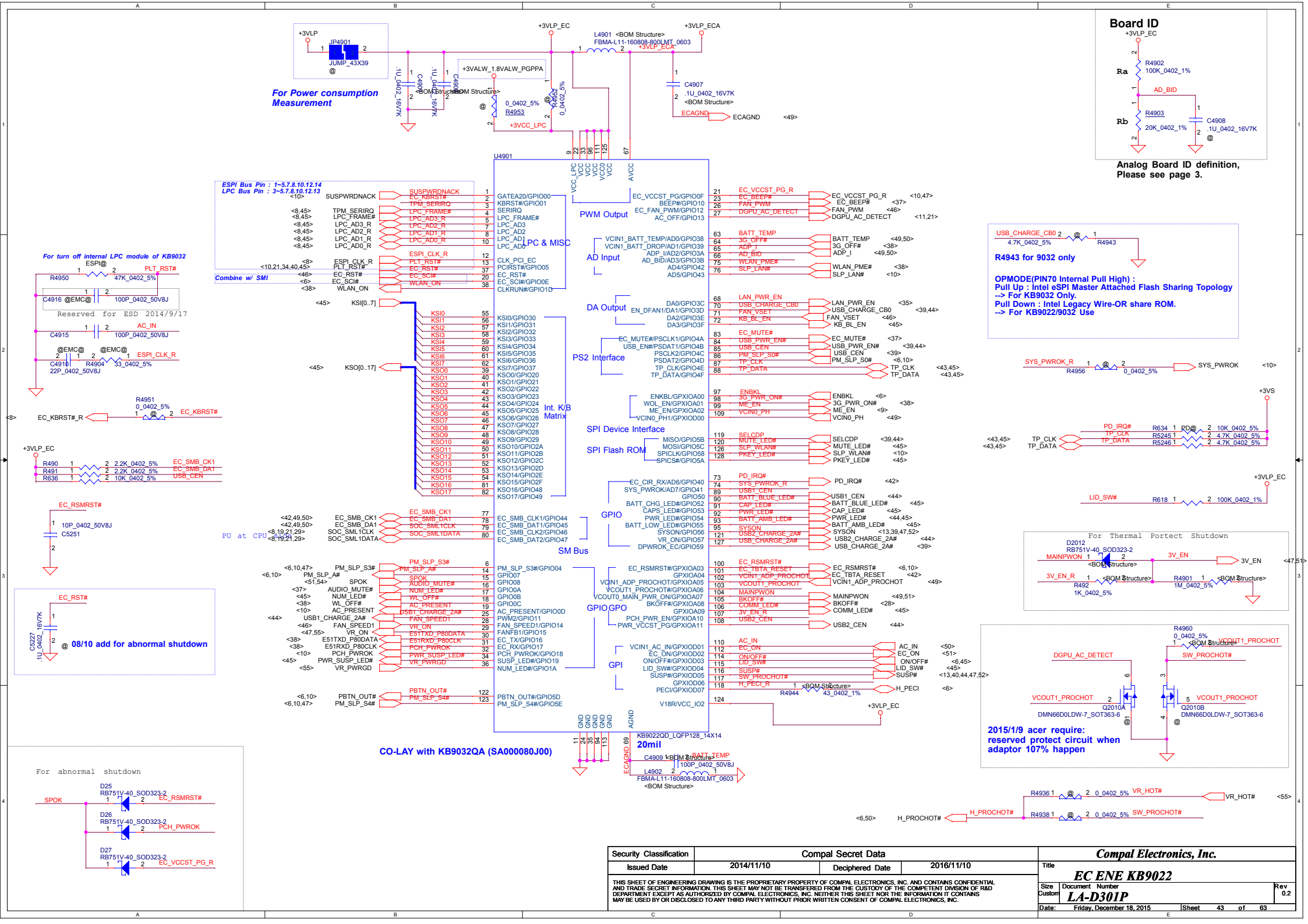


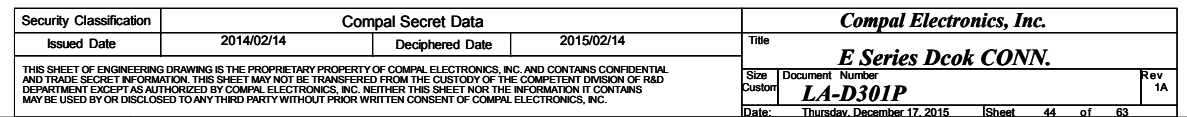
Figure 71. Alpine-Ridge SP Power Delivery



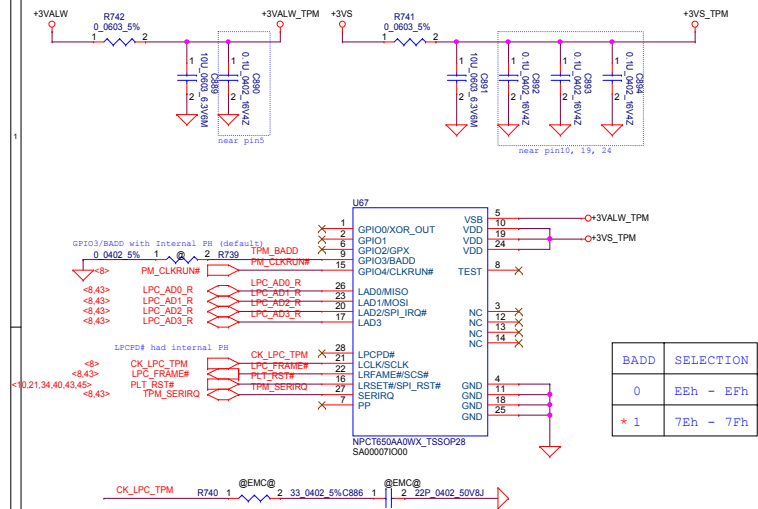
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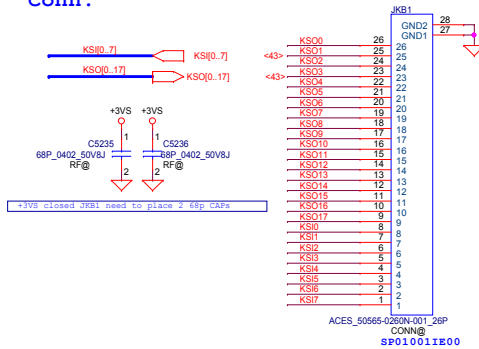




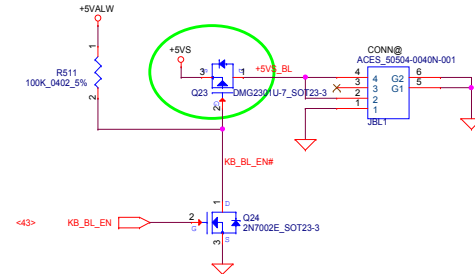
TPM



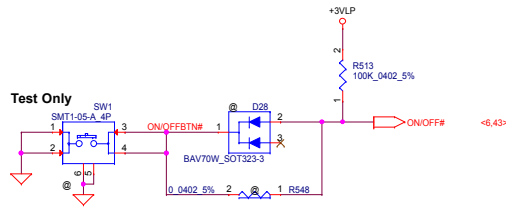
KB Conn.



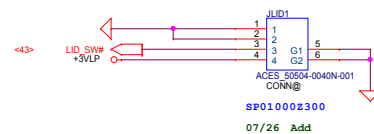
KB Backlight Conn



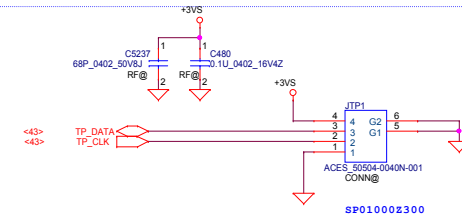
ON/OFF BTN



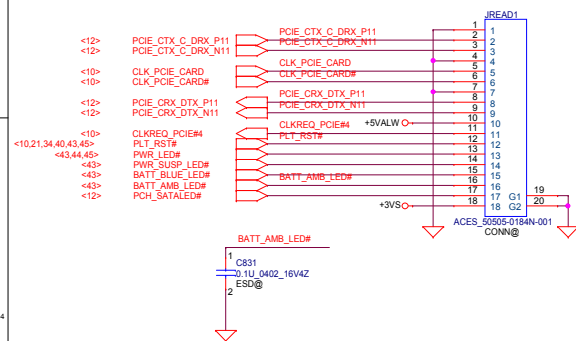
Lid Switch/B (Hall Effect Switch)



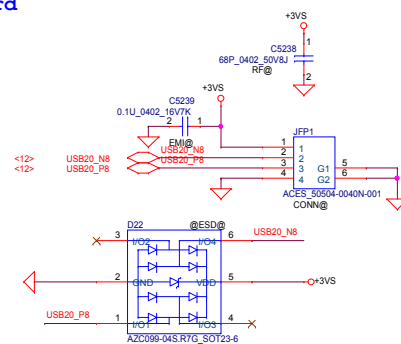
TP Conn.



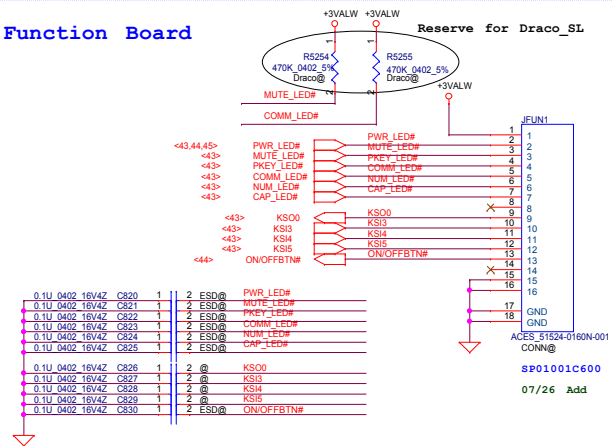
CardReader Board



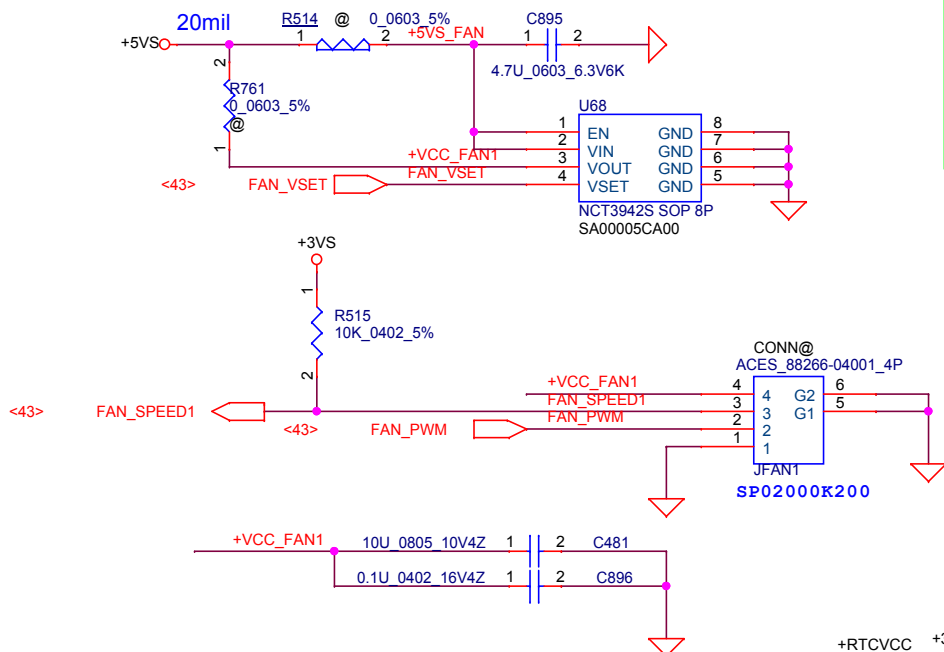
FP Board



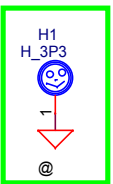
Function Board



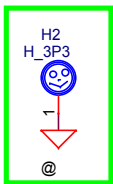
FAN Conn



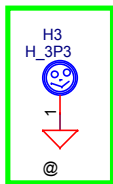
WIFI Stand off



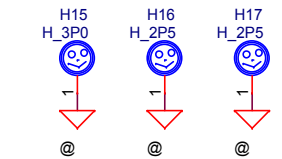
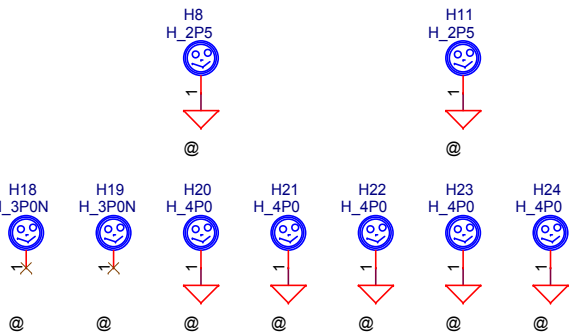
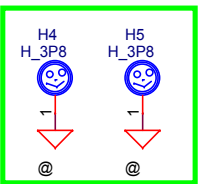
3G Stand off



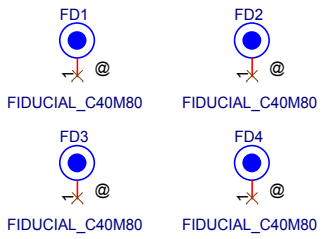
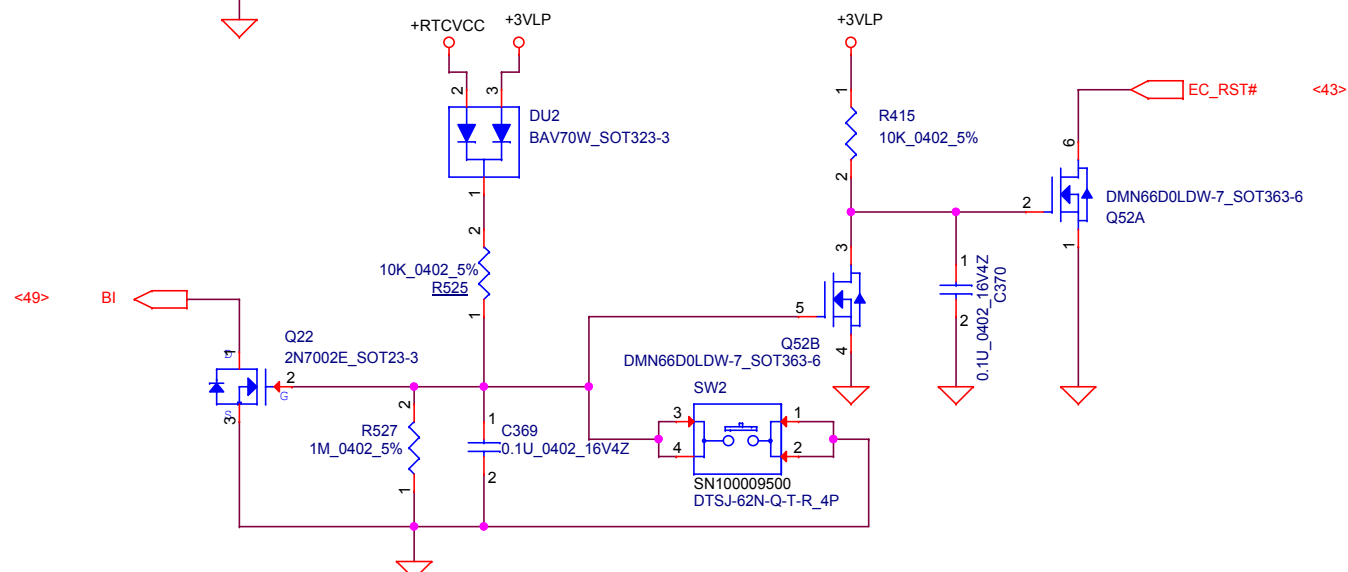
SSD Stand off



FAN Stand off

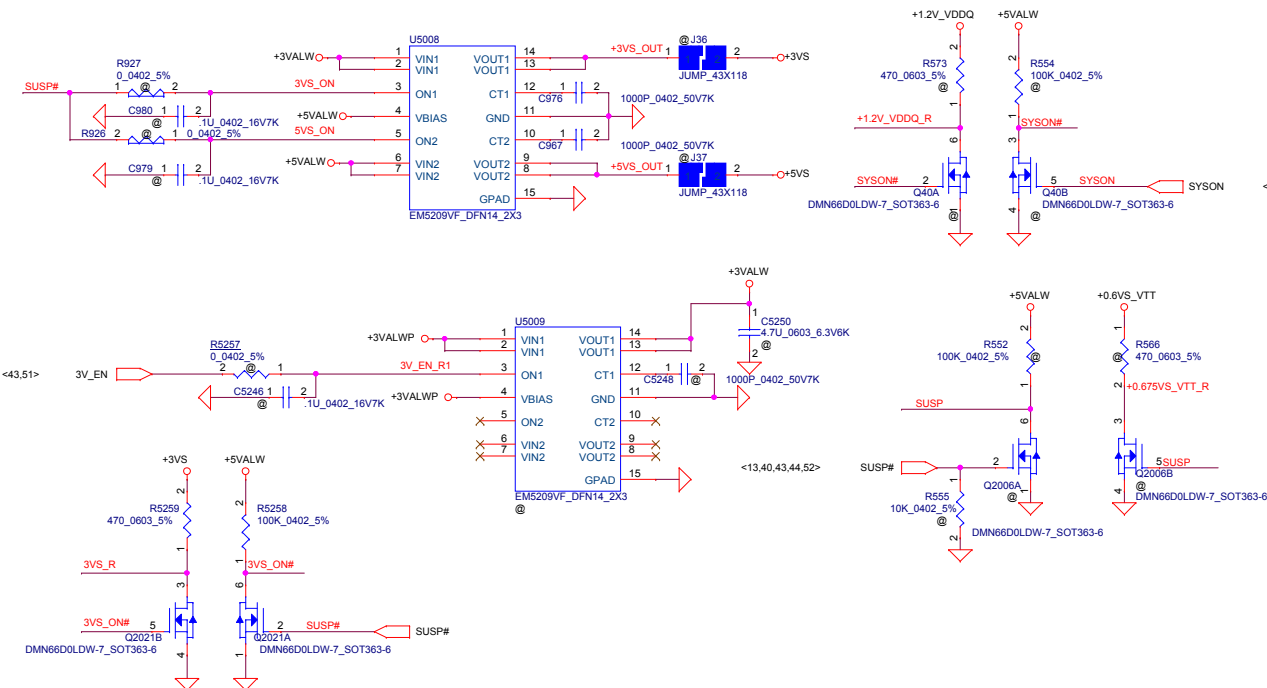


locate MB

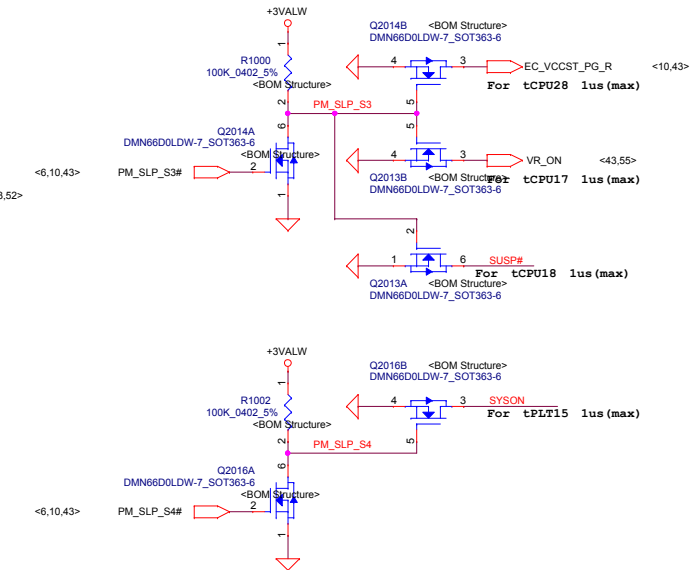


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				Size Custom	Document Number LA-D301P	Rev 1A
Date:				Thursday, December 17, 2015		
				Sheet	46 of 63	

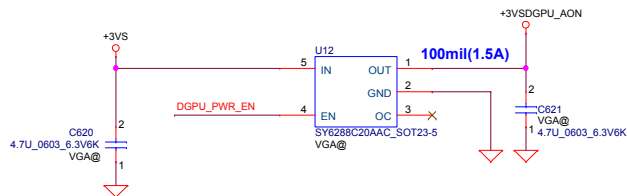
DC & VGA Interface



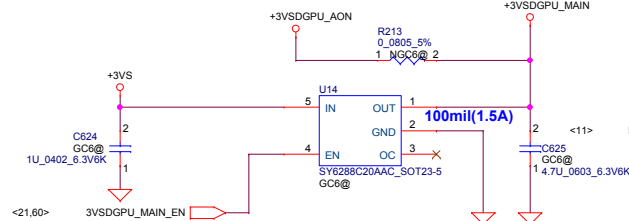
For Power Of f Sequence



+3VS to +3VSDGPU_AON for GPU



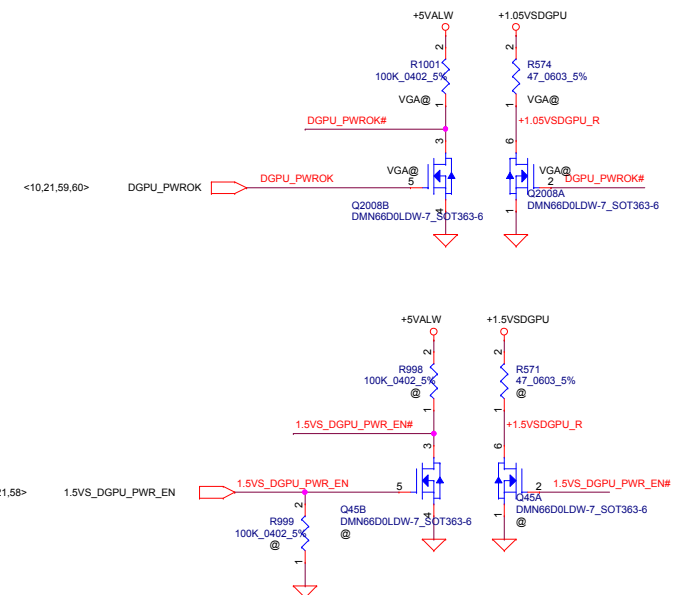
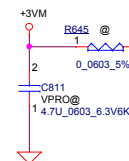
+3VS to +3VSDGPU_MAIN for GC6-2.0



3VSDGPU_MAIN_EN From GPU

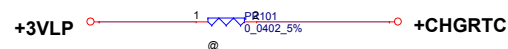
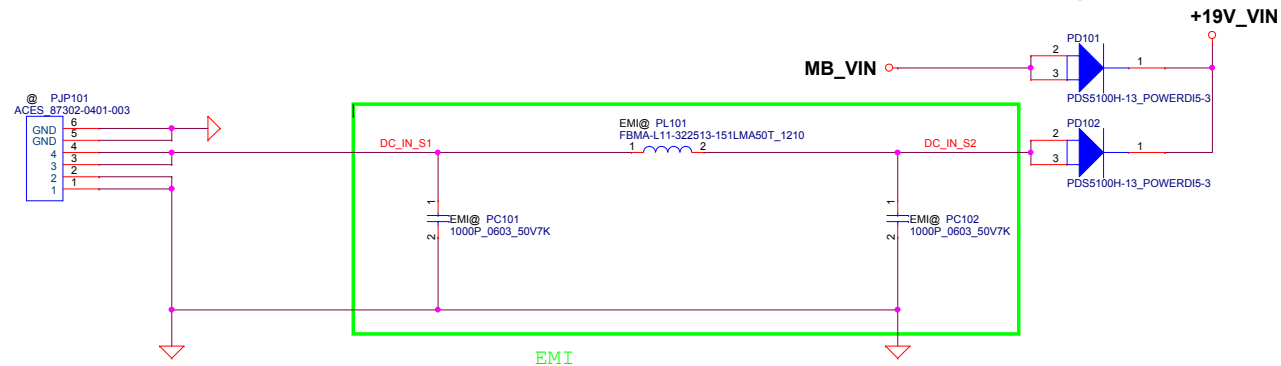
+3VALW to +3VM for Intel AMT

20mil(68mA)

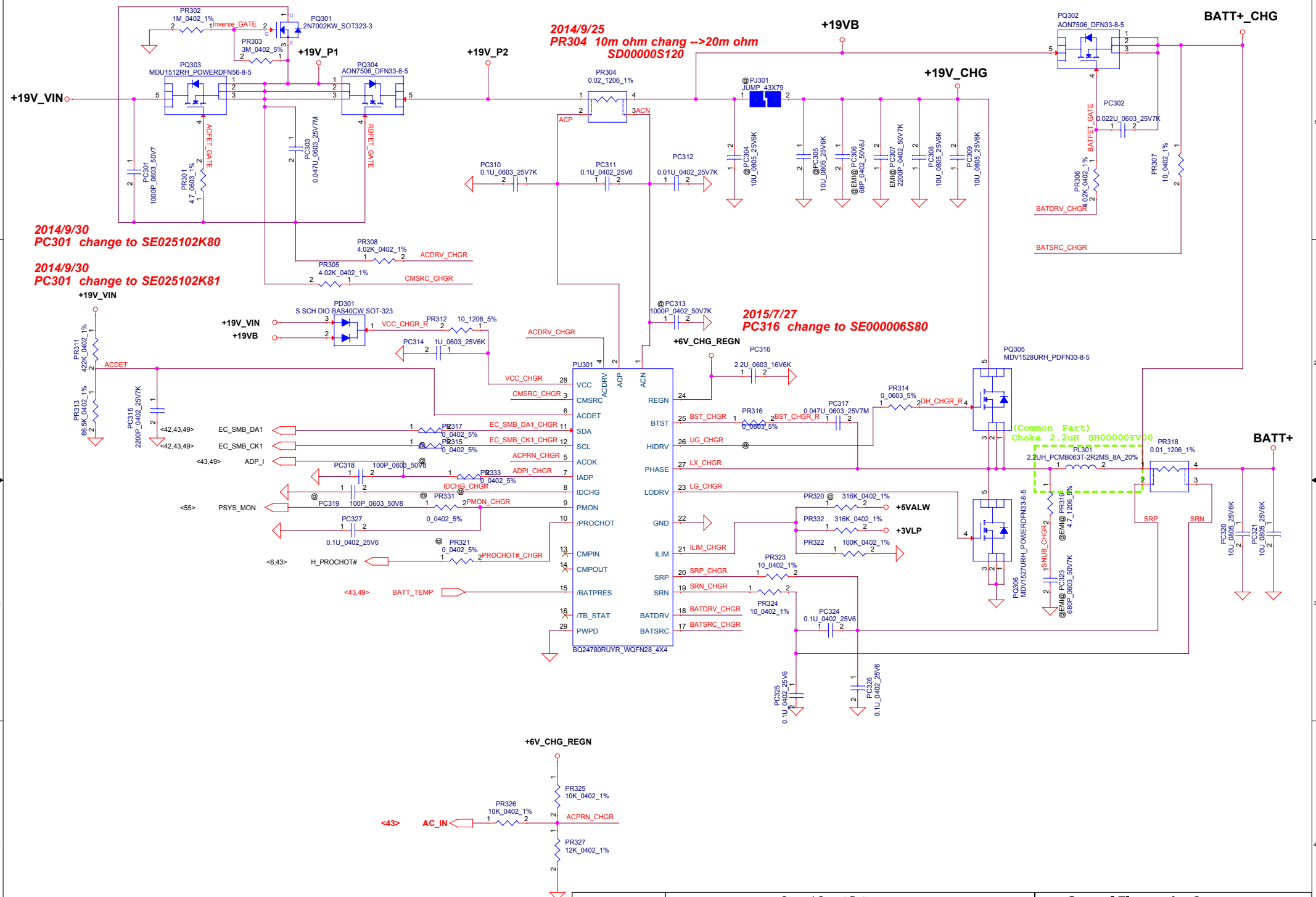


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				Custom	LA-D301P	0.2
				Date:	Friday, December 18, 2015	Sheet 47 of 63

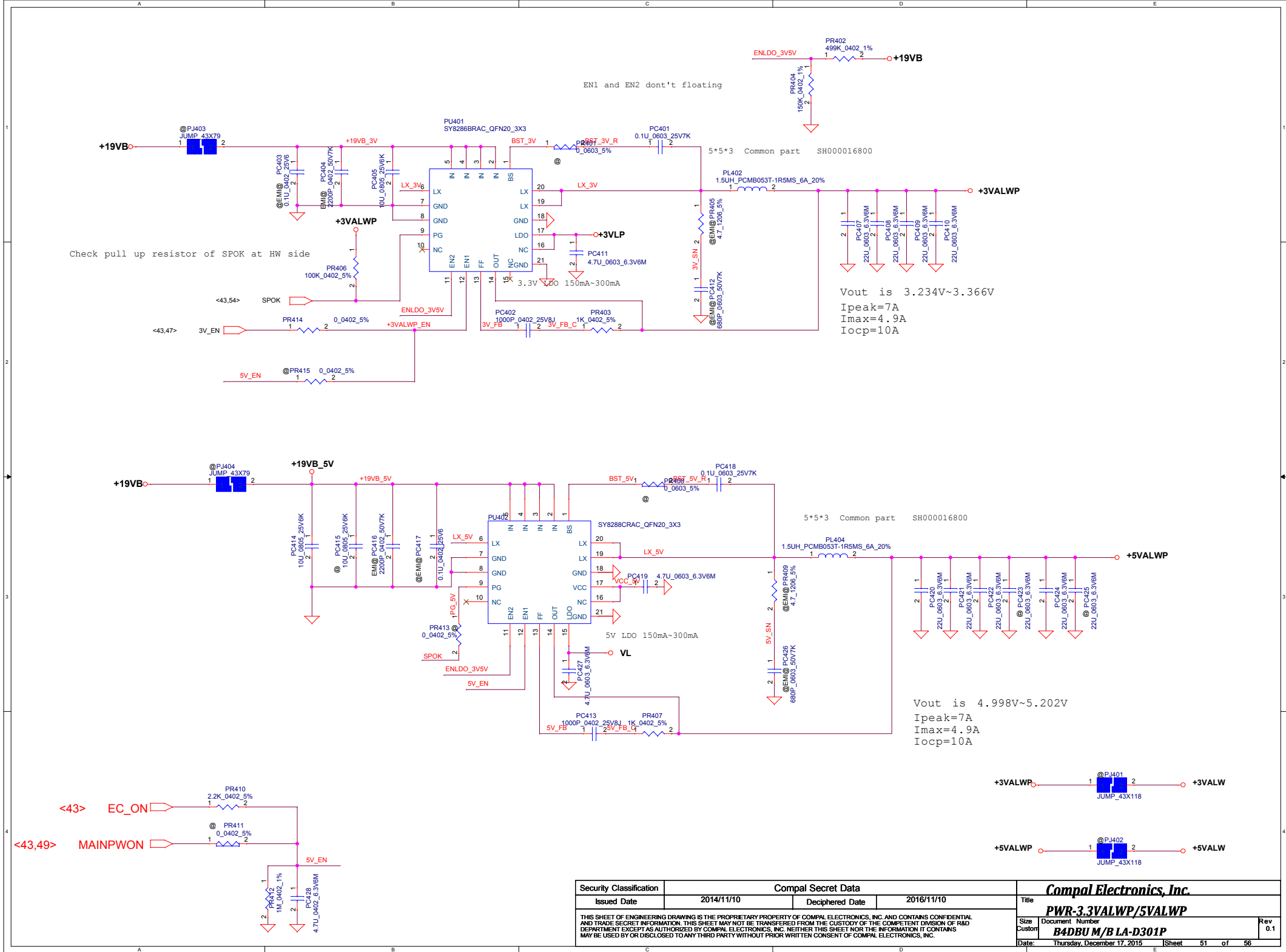
2015/7/8
PD101 and PD102 SCS00002F00 change to SCS00002M00



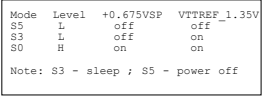
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Issued Date	2014/11/10	Deciphered Date	2016/11/10	Title	
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						Size		Document Number		Rev	
						Custom		B4DBU M/B LA-D301P		0.1	
						Date:		Thursday, December 17, 2015		Sheet 50 of 56	



```
Module model information
RT8207M_V1.mdd For Single layer
RT8207M_V2.mdd For Dual layer
```



```

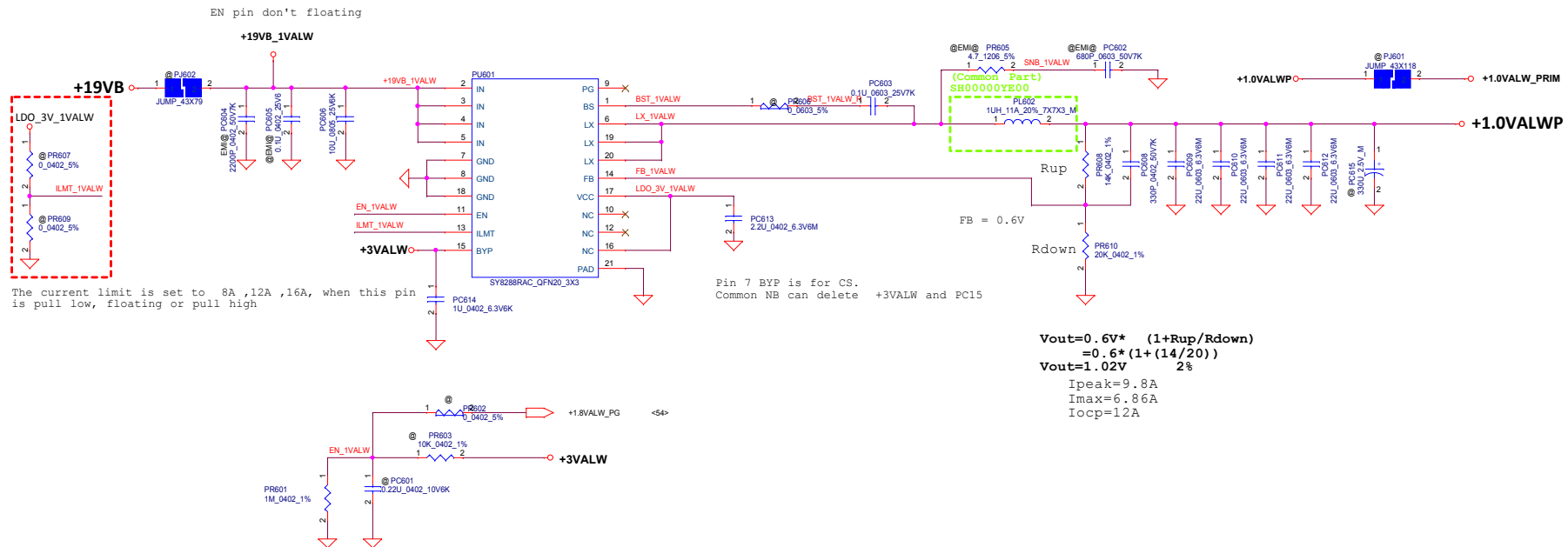
MOSFET: 3x3 DFN
H/S Rds(on): 23.2mohm(Typ), 27.8mohm(Max)
Idsm: 10.1A@Ta=25C, 8.1A@Ta=70C
L/S Rds(on): 13.5mohm(Typ), 16.5mohm(Max)
Idsm: 12A@Ta=25C, 9.5A@Ta=70C
Choke: 7x7x3
Rdc=14mohm(Typ), 15mohm(Max)

Switching Frequency: 285KHz
Ipeak=5A
Iocp=9.6A
OVP: 110%-120%
VFB=0.75V, Vout=1.2V
MOSFET footprint: S1S412DN

```

5/29 add PC526
In order to avoid capacitor decay

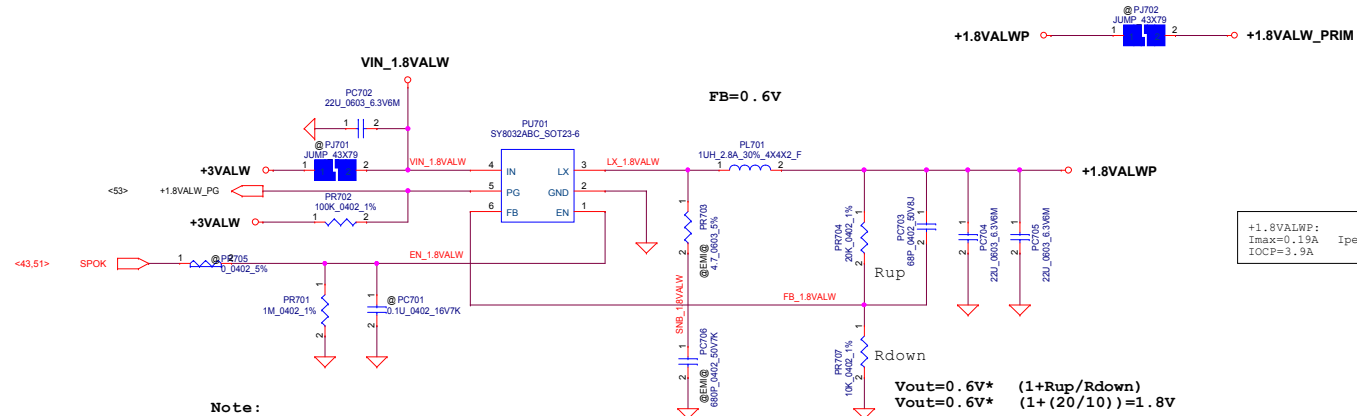
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Size	Document Number			Rev
Quantity				01
Date	Drawing Date 12/10/16			Issue



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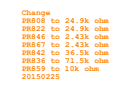
Module model information

SY8032_V2.mdd



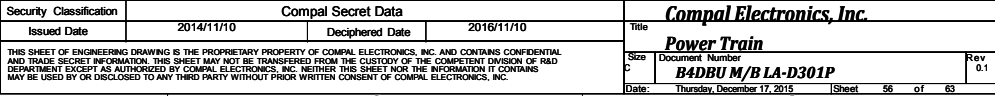
Note:
When design Vin=5V, please stuff snubber
to prevent Vin damage

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				Rev	0.1



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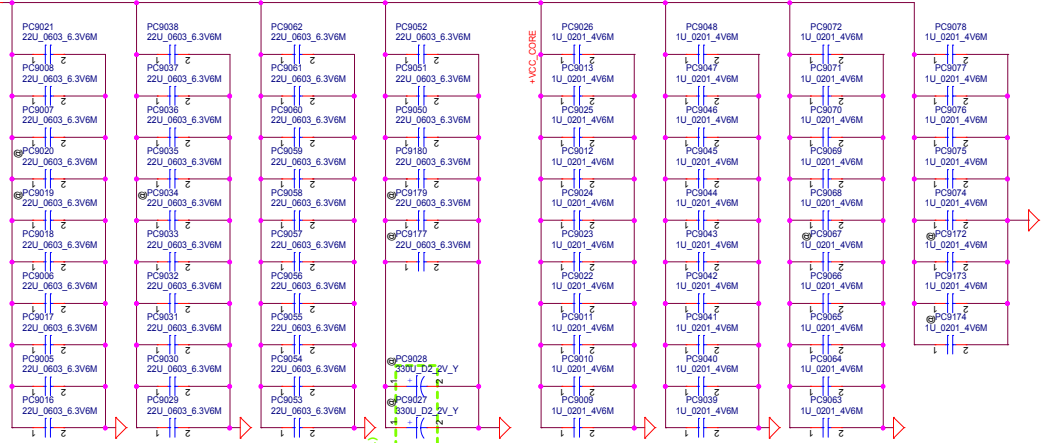
Size: Document Number: Rev: 01
B4DBU M/B LA-D301P
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Total VCORE Output Capacitor:

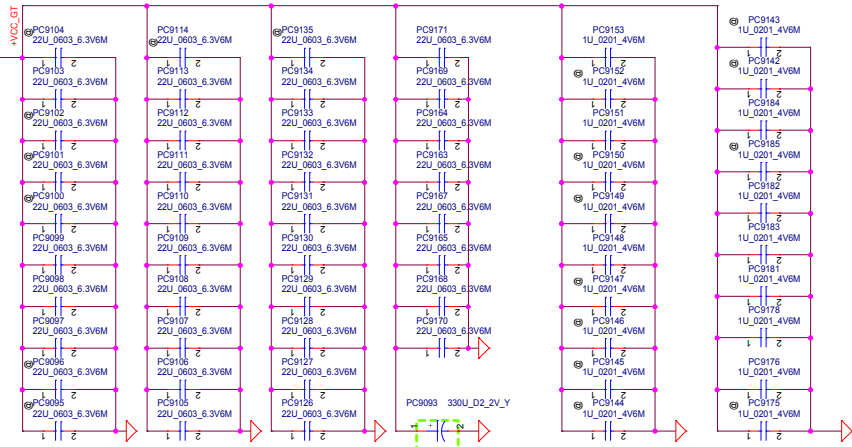
2015/07/09
22uF_0603_28PCS
1uF_0201_35PCS
UNPOP: 0603_3PCS, 0201_3PCS, 330uF_R0_2PCS

+VCC_CORE



20150709
D2*1 22uF_0603*30 1uF_0201*9
unpop: 22uF_0603*8 1uF_0201*11

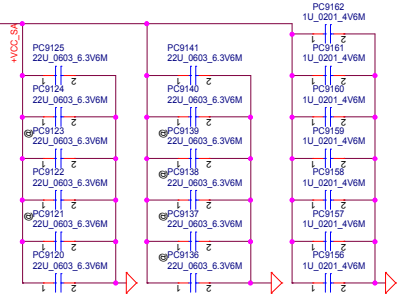
+VCC_GT



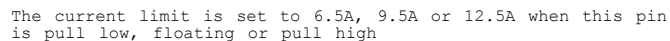
1u_0201 SE0000000200856
22u_0603 1 SE0000000C00

20140703
22uF_0603*6 1uF_0201*7
unpop: 22uF_0603*6

+VCC_SA

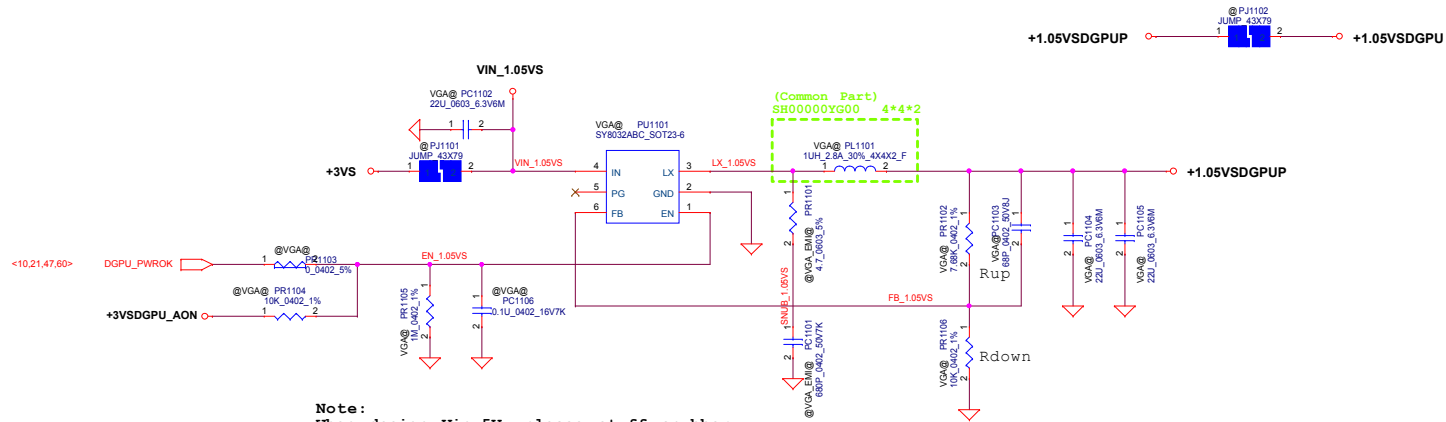


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				C	
				0.1	
				Date:	
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				Sheet	
				57	
				63	


$$\begin{aligned} V_{FB} &= 0.6V \\ V_{out} &= 0.6V * (1 + R_{up}/R_{down}) \\ V_{out} &= 0.6V * (1 + (30.9/20)) = 1.527 \end{aligned}$$

Module model information

SY8032_V2.mdd



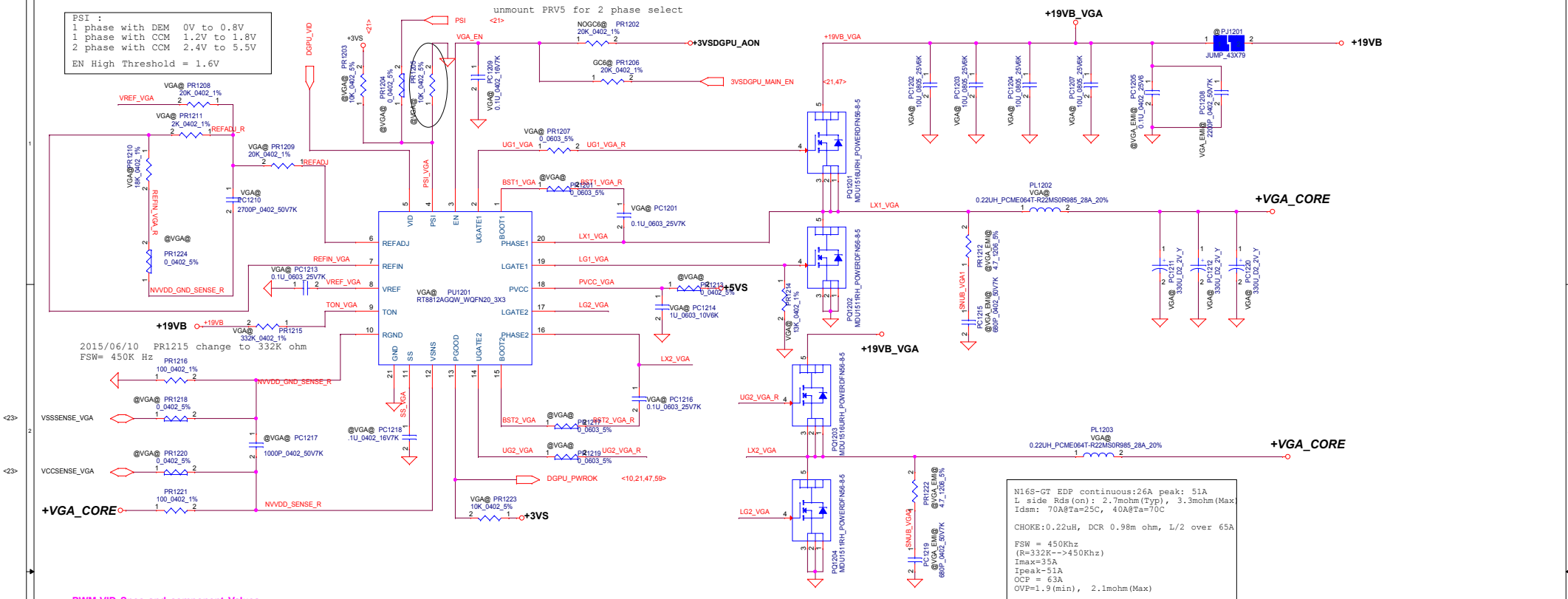
$$V_{out} = 0.6V * (1 + R_{up}/R_{down})$$

$$= 0.6V * (1 + (7.68/10)) = 1.061 \quad (1.01\%)$$

$$I_{max} = 0.77A, I_{peak} = 1.1A, I_{ocp} = 3.5A$$

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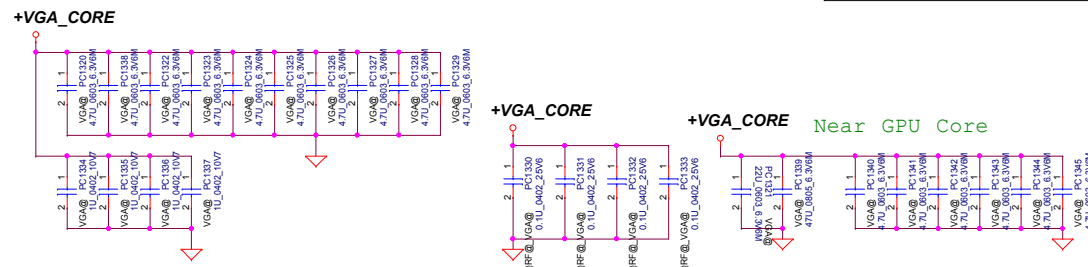
PSI :	
1 phase with DEM	0V to 0.8V
1 phase with CCM	1.2V to 1.8V
2 phase with CCM	2.4V to 5.5V
EN High Threshold	= 1.6V

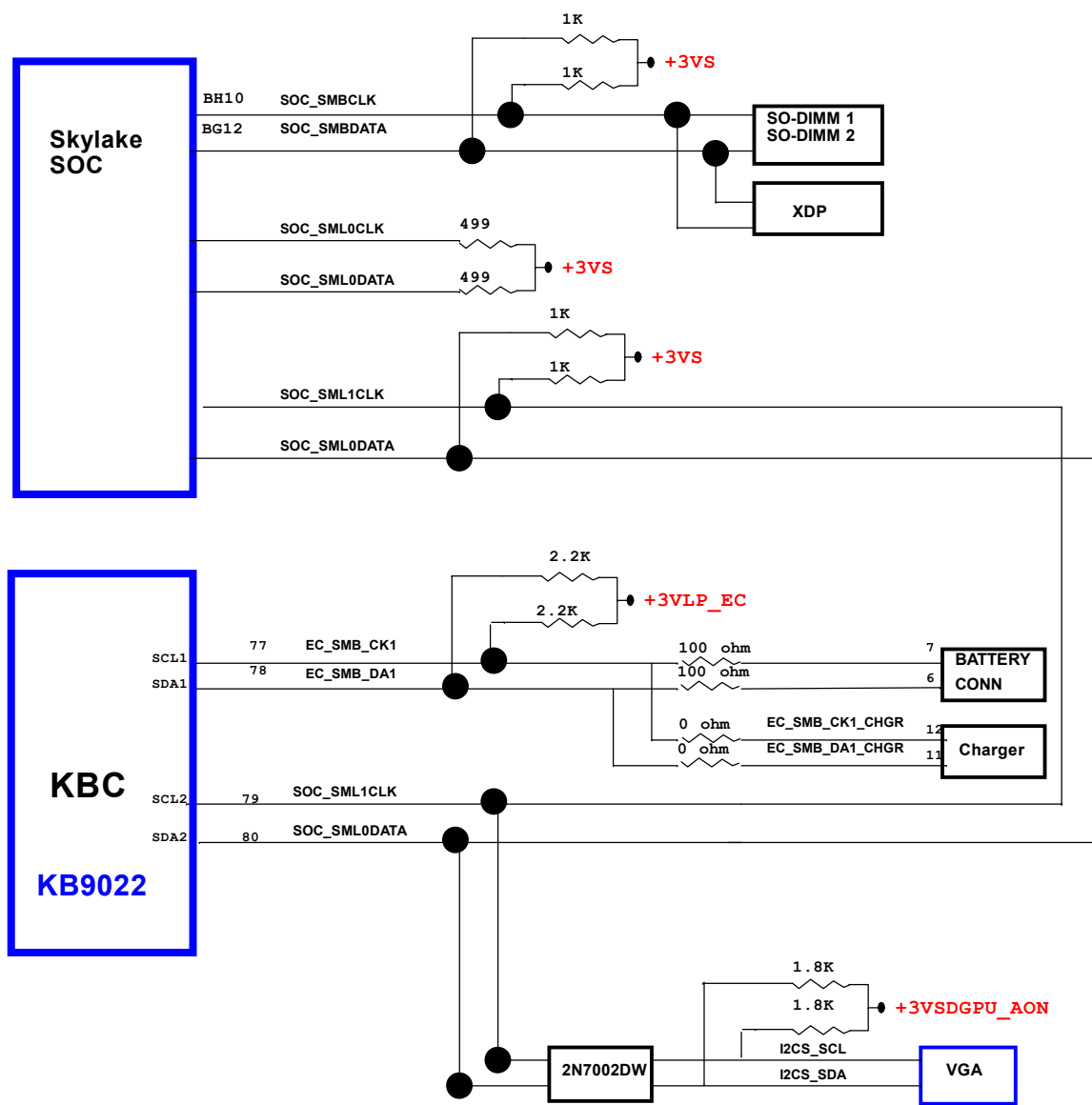


PWM-VID Spec and component Values

PWM-VID Spec		Config B	Config C	Config D
Vmin		0.6V	0.65V	0.9V
Vmax		1.2V	1.15V	1.15V
Vboot		0.9V	0.9V	1.028V
Voltage step		6.25mV	25mV	12.5mV
N of Voltage level		96	20	20
Rrefadj	PR	20K	39K	27K
Rref1	PR	20K	30K	7.5K
Rboot	PR	2K	3K	0
Rref2=PR1209 +PR1212	PR	18K	24K	6.2K
	PR	0	3K	1.74K
C	PC	2.7nf	1.8nf	5.6nf

N16S-GT
N16V-GM





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						Size		Document Number		Rev	
						Custom		B4DBU M/B LA-D301P		0.1	
						Date:		Thursday, December 17, 2015		Sheet 61 of 63	

*Page 1 of 1
for PWR*

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				Custom	B4DBU M/B LA-D301P	0.1
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EVT->DVT

0810

- 1. Remove RPC8
- 2. Change the BOM structure of CD36 and CD34 to @
- 3. Change UL3's part number to SA000028Y10
- 4. Change U67's part number to SA000071O10
- 5. Add U5004's part number SA00008E710
- 6. Change U5007's BOM structure to TBT@
- 7. Change U1's part number to SA00007UJ10
- 8. Remove U61, C818
- 9. Change BOM structure of RC62 and RC63 to POP
- 10. Connect RC18.2 to Codec PIN 31 (for MIC function)
- 11. Remove RC240
- 12. Add C5227
- 13. Add R5251, R5252
- 14. Change D44's part number to SC300003S00
- 15. change BOM structure PC@ to @

0812

- 1. JLID1. 4 Connecto to +3VLP
- 2. change type C connector's part number to LTCX006Z3BL
- 3. remove D16

0813

- 1. change type C connector JUSB2's footprint from lotes_ausb0139-p001a_24 to JAE_DX07S024XJ1_24P-T

0817

- 1.change back TYPE C connector to SP011504212
- 2.change D29 and D30's part number to SC300003S00, same as D44
- 3.remove R630,R631,R633,R665,R667,R668,R669,R671
- 4.C5126,C5121,C5118,C5117 change to @ for HDMI
- 5.C5201,C5202,C5197,C5196 change to 0201 for TBT
- 6.Add C5239 0.1u on +3VS (JFP1) for EMI
- 7.C480,C633 change to RF@ for RF
- 8.ADD C5237 68P on +3VS(JTP1) for RF
- 9.ADD C5238 68P on +3VS(JFP1) for RF
- 10.ADD C5232 68P on +3VS(JDMIC) for RF
- 11.ADD C5229, C5230, C5231 0.1u+2200p+68p on +19VB for RF
- 12.ADD C5235, C5236 68P*2 on +3VS(JKB) FOR RF
- 13.ADD C5228, R5253 00HM+22P (RPC9) FOR RF
- 14.ADD C5233 0.1u on +5VALW(JIO1) for EMI
- 15.ADD C5240 68P on +5VALW(JIO1) for RF
- 16.ADD C5241 @RF@ for RF
- 17.Change C5241's connection to ESPI_CLK_R
- 18. Change R5173's connection to EC_TBTA_RESET

0818

- 1. Change C5227 to @
- 2. Change C633 to @
- 3. Change C5179~C5182 package to 0201
- 4. Modify the connection of U26.9(G_INT2)

0819

- 1. Change package of R630, R631, R633, R665, R667, R668, R669, R671 to short pad
- 2. Add C5242, C5243, C5244, C5245 for EMI
- 3. Change package of U5005 to SOP8
- 4. R1579-->@, R1581-->POP

DVT->PVT

1008

- 1. C5244, C5243, C5242, C5245 change to EMI@
- 2. D17, D18, D19, D20, D21, D34, D23, D24 Change to SC40000AT00
- 3. R443, R444, R445 change to vpro@
- 4. R4903 change to 15K for DVT Board ID
- 5. R1579-->@, R1581-->POP
- 6. R5203-->@, R5173-->POP
- 7. UL3, U60 Change to SA000079400
- 8. SW1-->@
- 9. CL14 change to 0603
- 10. JREAD1 PIN10's connection from +3VALW to +5VALW
- 11. CD41, CD42, CD43 change to 0402
- 12 add 16M BIOS ROM on UC2

1012

- 1. Connect DET_SIG#_R to UCPU1 pin AY5

1015

- 1. Change below items to short pad :
RC238,RC245,RC55,RC56,RC12,RC130,RC131,
RC168,RC186,RC188,RC208,RC140,RC143,RC141,
RC192,RC175,RC148,RC173,RC154,RC198,RC209,
RC149,RC176,RC156,RC197,RC161,RC163,RC172,
RC167,RC187,RC162,RC171,RC169,RC164,RC190,
RC152,RD45,RD47,RD46,R550,R549,R23,R5248,
R664,RC229,RC19,RC20,R486,R487,R873,R441,
R442,R661,R5193,R1580,R5210,R5209,R5192,
R5194,R5197,R5198,R4953,R514,R645,
2. Change U5007's part number to SA00008C310

1016

- 1. Update power schematic 1016

1016a

- 1. Add R5254, R5255 for Draco_SL reserve

1018

- 1.Change R23, R5248, RC130, RC131, R486, R487 back to 0ohm resistor

1027

- 1. Change U67's part number to SA000071O00
- 2. SUSCLK R5252 POP->@
- 3. R5250 TBT@->@TBT@
- 4. Add LAN Chip UL1 R3 Part Number SA000081G50
- 5. Replace SP050006F00 to SP050006B10

PVT->PreMP

1209

- 1. Change R1581 to @
- 2. Change R1579 to TBT@
- 3. Change U60 to @
- 4. Change UC3's to 3VM
- 5. BOARD ID Change to PreMP Value
- 6. Add RC248, RC249

1216

- 1. R525 changes to 10K
- 2. C5232 changes to 0.1U
- 3. PIN UC1.R10 connect to +3VALW PRIM with 2.2K resistor
- 4. add U5008 for 3VALW and 3VALWP

1217

- 1. U5009.4 Connect to 3VLAWP
- 2. Add Q2021, R5258, R5259 for Discharge
- 3. Q2021.3 Connect to SUSP#

1218

- 1. Add C5251 for EC_RSMRST#

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